

AIROC™ Automotive Bluetooth® Low Energy 5.4

General description

The Infineon AIROC™ CYW89829 is a high-performance, ultra-low-power and “Secure” MCU + Bluetooth® LE platform, purpose-built for industrial and automotive applications. It combines a high-performance microcontroller with Bluetooth® LE (5.4) connectivity, high-performance analog-to-digital conversion audio input, I2S/PCM, CAN, LIN for automotive use cases and other standard communication and timing peripherals. CYW89829 employs high level of integration to minimize external components, reducing the device footprint and costs associated with implementing Bluetooth® Low Energy solutions. CYW89829 is the optimal solution for industrial and automotive use cases such as car access, battery management system, automotive sensors, and other applications requiring automotive AECQ-100 grade-2 qualification. CYW89829 has an integrated PA with 10 dBm RF output that enables applications requiring high link budget and robust RF performance.

Features

- **32-bit application core subsystem**
 - 48/96 MHz Arm® Cortex®-M33 CPU with single-cycle multiply and memory protection unit (MPU)
 - ARMv8-M architecture
 - CMOS 40 nm process
 - User-selectable core logic operation at either 1.1 V or 1.0 V
 - Active CPU current slope with 1.1 V core operation
 - Cortex®-M33: 40 µA/MHz
 - Active CPU current slope with 1.0 V core operation
 - Cortex®-M33: 22 µA/MHz
 - Datawire (DMA) controller with sixteen channels
 - 32 KB cache for greater XIP performance with lower power
- **Memory subsystem**
 - 256 KB SRAM with power and data retention control
 - OTP eFuse array for security provisioning
- **Bluetooth® Low Energy subsystem**
 - 48-MHz Arm® Cortex®-M33 CPU with 2.4 GHz RF transceiver with 50 Ω antenna drive
 - 8 Mb integrated flash
 - Digital PHY
 - Link layer engine supporting master and slave modes
 - Programmable TX power: up to 10 dBm
 - RX sensitivity:
 - LE-1 Mbps: -98 dBm
 - LE-2 Mbps: -95 dBm
 - Coded PHY 500 kbps (LE-LR): -101 dBm
 - Coded PHY 125 kbps (LE-LR): -106 dBm
 - 5.2 mA TX (0 dBm), 19.3 mA TX (10 dBm), and 5.7 mA RX (LE 1 Mbps) current with 3.0 V supply and using internal buck converter
 - CYW89829 link layer engine can support up to 16 connections of any combinations between central and peripheral devices simultaneously, for example, 13 central devices and 3 peripheral devices, or 3 central devices and 13 peripheral devices
 - Angle of Arrival (AoA) and Angle of Departure (AoD)^[1]

Note

1. For the end users interested in AoA/AoD solutions such as RTLS, Direction Finding, and more, it will be necessary for customers and partners to develop or obtain licenses for different system components to realize the final solution.

Features

- **Low-power 2.7 V to 3.6 V operation**

- Six power modes for fine-grained power management
- Deep Sleep mode current of 6.7 μ A with 64 KB SRAM retention
- On-chip DC-DC buck converter

- **Flexible clocking options**

- 8-MHz internal main oscillator (IMO) with $\pm 2\%$ accuracy
- Ultra-low-power 32 kHz internal low-speed oscillator (ILO)
- Two oscillators: High-frequency (24 MHz) for radio PLL and low-frequency (32 kHz watch crystal) for LPO
- 48-MHz low power IHO (internal oscillator)
- Frequency-locked loop (FLL) for multiplying IMO frequency
- Integer and fractional peripheral clock dividers

- **8 Mb integrated flash**

- Execute-in-place (XIP) from flash
- On-the-fly encryption and decryption
- Support for DDR
- More than 100,000 erase/write cycles
 - More than 20-year data retention

- **Serial communication blocks**

- Three run-time configurable serial communication blocks (SCBs)
 - First SCB: Configurable as SPI or I²C
 - Second SCB: Configurable as SPI or UART
 - Third SCB: Configurable as I²C or UART

All three SCBs can be configured for I2C or SPI to use at the same time. However, only two SCBs can be configured for UART to use at the same time.

- **Audio subsystem**

- Two pulse density modulation (PDM) channels and one I²S channel with time division multiplexed (TDM) mode

- **Timing and pulse-width modulation**

- Seven 16-bit and two 32-bit Timer/counter/ pulse-width modulator (TCPWM) blocks, for MCU. Multiple PWMs needed for color LEDs.
- PWM supports center-aligned, edge, and pseudo-random modes

- **ADC and MIC**

- 12-bit sigma-delta switched cap ADC for audio and DC measurements

- **Up to 26 programmable GPIOs**

- One I/O port (8 I/Os) enables Boolean operations on GPIO pins; available during system Deep Sleep
- Programmable drive modes, strengths, and slew rates
- Two overvoltage-tolerant (OVT) pins

- **Security built into platform architecture**

- ROM-based root of trust via uninterruptible “Secure Boot”
- Step-wise authentication of execution images
- Secure execution of code in execute-only mode for protected routines
- All debug and test ingress paths can be disabled
- Up to four protection contexts (one available for customer code)
- Secure debug support via authenticated debug token

Features

- **Cryptography hardware**

- Hardware acceleration for symmetric cryptographic methods and hash functions
- True Random Number Generation (TRNG) function

- **Packages**

- 77-ball BGA, 8.0 × 7.0 × 1.0 mm height with 0.8 mm pitch (AEC-Q100 grade-2 certified)

Eclipse IDE for Modustoolbox™ software

Eclipse IDE for Modustoolbox™ software

Modustoolbox™ software is Infineon's comprehensive collection of multi-platform tools and software libraries that enable an immersive development experience for creating converged MCU and wireless systems. It is:

- Comprehensive - it has the resources you need
- Flexible - you can use the resources in your own workflow
- Atomic - you can get just the resources you want

Infineon provides a large collection of code **repositories on GitHub**. This includes:

- Board support packages (BSPs) aligned with Infineon kits
- Low-level resources, including a hardware abstraction layer (HAL) and peripheral driver library (PDL)
- Middleware enabling industry-leading features such as Bluetooth® Low Energy, and mesh networks
- An extensive set of thoroughly tested **code example applications**

Note : The HAL provides a high-level, simplified interface to configure and use the hardware blocks on Infineon MCUs and SoCs. It is a generic interface that can be used across multiple product families. You can leverage the HAL's simpler and more generic interface for most of an application, even if one portion requires fine-grained control.

ModusToolbox™ software is IDE-neutral and easily adaptable to your workflow and preferred development environment. It includes a Project Creator, a Library Manager, a BSP Assistant, peripheral and library configurators, as well as the optional Eclipse IDE for the ModusToolbox™, as **Figure 1** shows. For information on using Infineon tools, refer to the documentation delivered with ModusToolbox™ software.

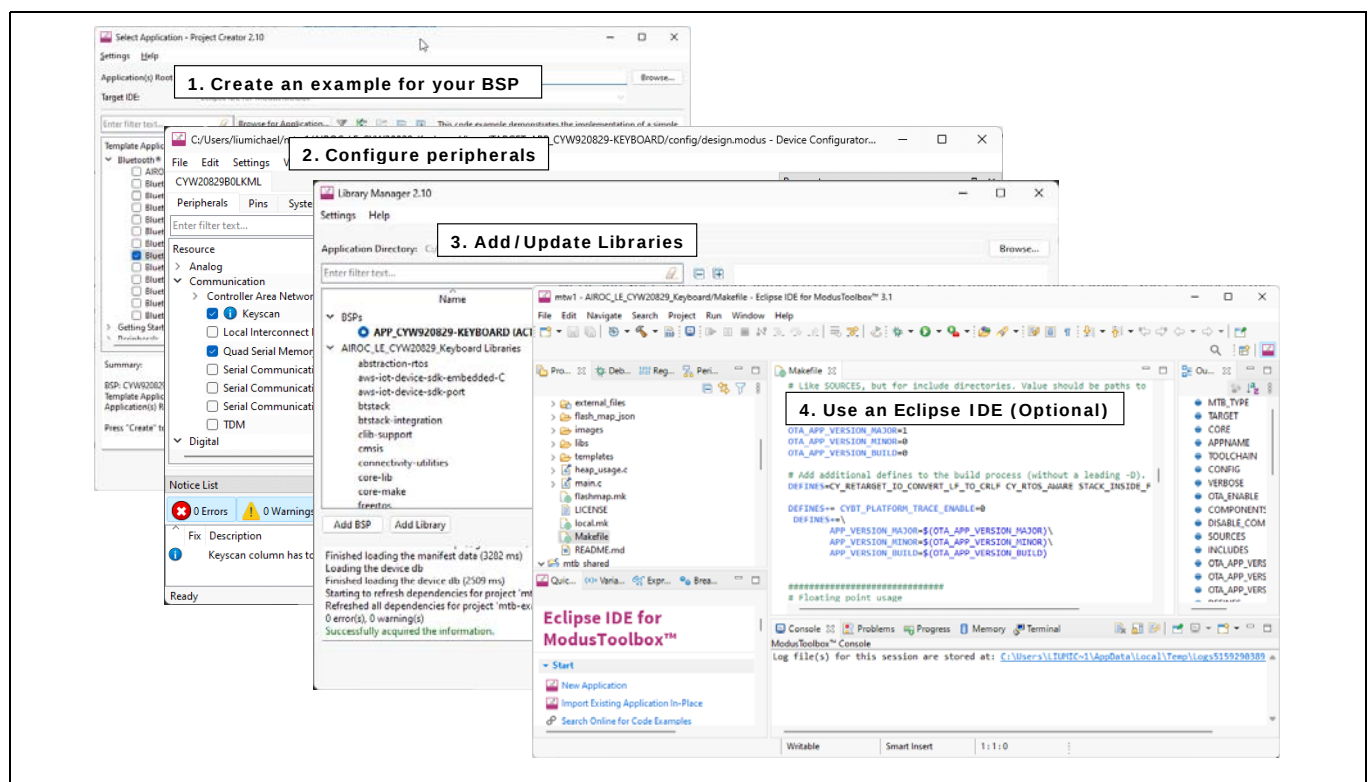


Figure 1 ModusToolbox™ software tools

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Block diagram

1 Block diagram

Figure 2 shows the major subsystems and a simplified view of their interconnections. The color coding shows the lowest power mode where a block is still functional. For example, the SRAM is functional down to DS-RAM mode.

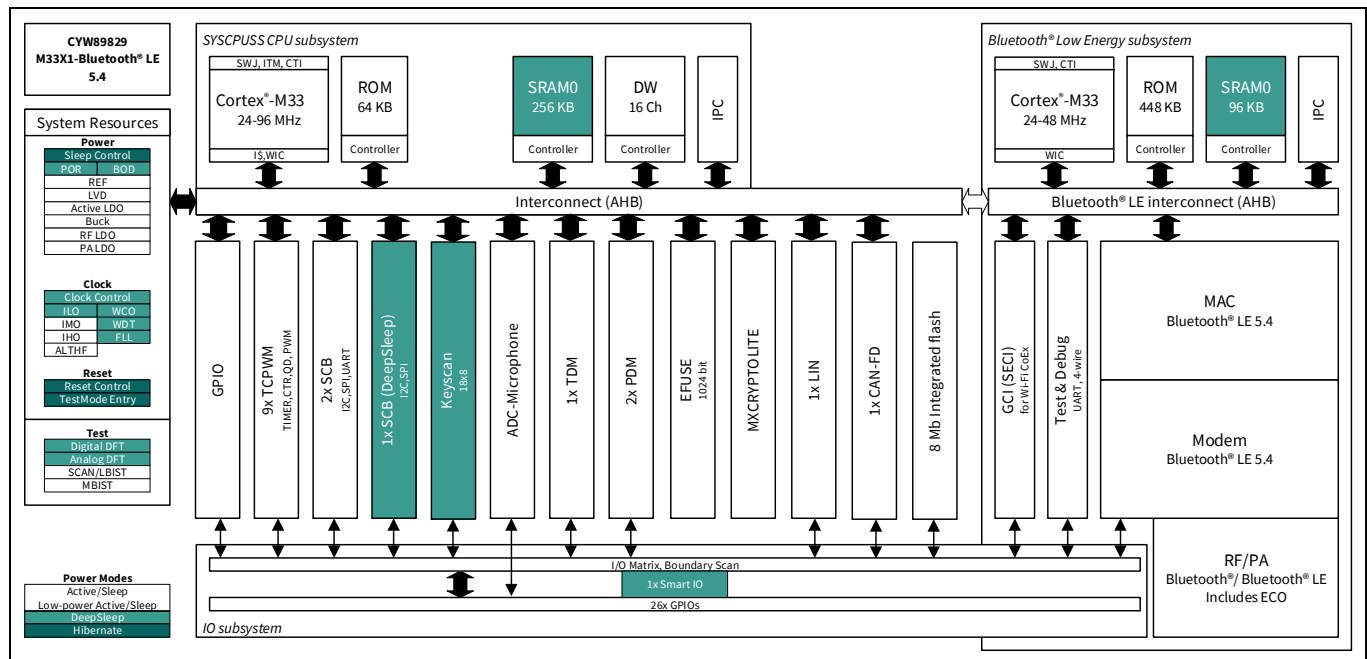


Figure 2 Functional block diagram

The AIROC™ CYW89829 devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware. All device interfaces can be permanently disabled (device security) for applications concerned about attacks due to a maliciously reprogrammed device. All programming, debug, and test interfaces are disabled when maximum device security is enabled. The security level is settable by the user.

Complete debug-on-chip functionality enables full device debugging in the final system using the standard production device. It does not require special interfaces, debugging ports, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The Eclipse IDE for ModusToolbox™ and Integrated Development Environment (IDE) provide fully integrated programming and debug support for these devices. The SWJ (SWD and JTAG) interface is fully compatible with industry-standard third party probes. With the ability to disable debug features, with very robust flash protection, and by allowing customer-proprietary functionality to be implemented in on-chip programmable blocks, CYW89829 provides a very high level of security.

Functional description

2 Functional description

The following sections provide an overview of the features, capabilities and operation of each functional block identified in the block diagram in [Figure 2](#). For more detailed information, see the following documentation.

• Board support package (BSP) documentation

BSPs are available on [GitHub](#). They are aligned with Infineon kits and provide files for basic device functionality such as hardware configuration files, startup code, and linker files. The BSP also includes other libraries that are required to support a kit. Each BSP has its own documentation, but typically includes an API reference such as the example [here](#). This [search link](#) finds all currently available BSPs on the Infineon [GitHub](#) site.

• Hardware abstraction layer (HAL) API reference manual

The Infineon HAL provides a high-level interface to configure and use hardware blocks on Infineon MCUs. It is a generic interface, used across multiple product families. HAL's is a simpler and more generic interface for most of an application, even if one portion requires finer-grained control. See [HAL API Reference](#) for more information. Example applications that use the HAL, download it automatically from the GitHub repository.

2.1 CPU and memory subsystem

The AIROC™ CYW89829 has multiple bus masters, as [Figure 2](#) shows. They are: CPU, datawire, QSPI, and a crypto block. Generally, all memory and peripherals can be accessed and shared by all bus masters through multi-layer Arm® AMBA high-performance bus (AHB) arbitration. An interprocessor communication block (IPC) provides communication between the CPU and the Bluetooth® LE sub-system.

2.1.1 CPU

The Cortex®-M33 has single-cycle multiply and a memory protection unit (MPU). It can run at up to 96 MHz in LP mode and 48 MHz in ULP mode. This is the main CPU, designed for a short interrupt response time, high code density, and high throughput.

Cortex®-M33 implements a version of the Thumb instruction set based on Thumb-2 technology (defined in the [Armv8-M architecture reference manual](#)).

The main MCU also implements device-level security, safety, and protection features. Cortex®-M33 provides a secure, interruptible boot function. This guarantees that post boot, system integrity is checked and memory and peripheral access privileges are enforced.

The CPU has the following power draw, at VDDD = 3.0 V and using the internal buck regulator.

Table 1 Active current slope at VDDD = 3.0 V using the internal buck regulator

System power mode		
CPU	ULP	LP
	22 µA/MHz	40 µA/MHz

The CPU can be selectively placed in Sleep and Deep Sleep power modes as defined by Arm®. The CPU also implements a Deep Sleep RAM (DS-RAM) mode in which almost all the circuits except RAM are powered OFF. Data in RAM is retained to maintain state. Upon exit, the CPU goes through a reset but can use the data in RAM to skip software initialization.

The CPU also has nested vectored interrupt controllers (NVIC) for rapid and deterministic interrupt response, and wakeup interrupt controllers (WIC) for CPU wakeup from Deep Sleep power mode.

CYW89829 has a debug access port (DAP) that acts as the interface for device programming and debug. An external programmer or debugger (the “host”) communicates with the DAP through the device serial wire debug (SWD) or joint test action group (JTAG) interface pins. Through the DAP (and subject to device security restrictions), the host can access the device memory and peripherals as well as the registers in the CPU.

CPU debug and trace features are as follows:

- Six hardware breakpoints and four watchpoints, serial wire viewer (SWV), and printf()-style debugging through the single wire output (SWO) pin.

Functional description**2.1.2 Interrupts**

The CPU has interrupt request lines (IRQ), with the interrupt source 'n' directly connected to IRQn.

Each interrupt supports eight configurable priority levels. One system interrupt can be mapped to the CPU non-maskable interrupts (NMI). Multiple interrupt sources are capable of waking the device from Deep Sleep power mode using the WIC.

2.1.3 Datawire

The Datawire is a light weight DMA controller with 16 channels, which support CPU-independent accesses to memory and peripherals. The descriptors for the channels are in SRAM and the number of descriptors is limited only by the size of the memory. Each descriptor can transfer data in two nested loops with configurable address increments to the source and destination.

2.1.4 Cryptography accelerator (Cryptolite)

A combination of HW and SW is able to support several cryptographic functions. Specifically it supports the following functions:

- Encryption/decryption
 - AES-128 hardware accelerator with following supported modes:
 - Electronic Code Book (ECB)
 - Cipher Block Chaining (CBC)
 - Cipher Feedback (CFB)
 - Output Feedback (OFB)
 - Counter (CTR)
- Hashing
 - Secure Hash Algorithm (SHA-256) hardware accelerator
- Message Authentication Functions (MAC)
 - Hashed Message Authentication Code (HMAC) acceleration using SHA-256 hardware
- True Random Number Generator (TRNG)
- Vector unit hardware accelerator
 - Digital Signature Verification using RSA
 - Digital Signature Verification using ECDSA

2.1.5 Protection units

CYW89829 has multiple types of protection to control erroneous or unauthorized access to memory and peripheral registers.

Protection units support memory and peripheral access attributes including address range, read/write, code/data, privilege level, secure/non-secure, and protection context.

Protection units are configured at "Secure Boot" to control access privileges and rights for bus masters and peripherals. Up to eight protection contexts ("Secure Boot" is in protection context 0) allow access privileges for memory and system resources to be set by the "Secure Boot" process per protection context by bus master and code privilege level. Multiple protection contexts are available.

2.1.6 AES-128

The AES-128 component to accelerate block cipher functionality. This functionality supports forward encryption of a single 128 bit block with a 128 bit key. SHA-256 component to accelerate hash functionality. This component supports message schedule calculation for a 512-bit message chunk and processing of a 512-bit message chunk.

Functional description**2.1.7 Vector unit (VU)**

The VU component to accelerate asymmetric key cryptography (for example, RSA and ECC). This component supports large integer multiplication, addition, and so on. The TRNG component based on a set of ring oscillators which includes a HW health monitor.

2.1.8 Controller area network flexible data-rate (CAN FD)

CYW89829 supports the CAN FD controller that supports one CAN FD channel. All the CAN FD controllers are compliant with the ISO 11898-1:2015 standard; an ISO 16845:2015 certificate is available. It also implements the time-triggered CAN (TTCAN) protocol specified in ISO 11898-4 (TTCAN protocol levels 1 and 2) completely in hardware. All functions concerning the handling of messages are implemented by the RX and TX handlers. The RX handler manages message acceptance filtering, transfer of received messages from the CAN core to a message RAM, and provides receive-message status. The TX handler is responsible for the transfer of transmit messages from the message RAM to the CAN core, and provides transmit-message status.

2.1.9 Local interconnect network (LIN)

CYW89829 contains a LIN channel. Each channel supports transmission/reception of data following the LIN protocol according to ISO standard 17987. Each LIN channel connects to an external transceiver through a 3-pin interface (including an enable function) and supports master and slave functionality. Each block also supports classic and enhanced checksum, along with break detection during message reception and wake-up signaling. Break detection, sync field, checksum calculations, and error interrupts are handled in hardware.

2.1.10 Real time clock (RTC)

- Year/Month/Date, Day-of-week, Hour: Minute: Second fields
- 12 and 24 hour formats
- Automatic leap-year correction

2.1.11 Memory

CYW89829 contains the SRAM, ROM, eFuse, and 8 Mb integrated flash memory blocks.

- **SRAM:** CYW89829 has 256 KB of SRAM. The power control and retention granularity is 64 KB blocks allowing the user to control the amount of memory retained in Deep Sleep. Memory is not retained in Hibernate mode.
- **ROM:** The 64-KB ROM, also referred to as the supervisory ROM (SROM), provides code (ROM Boot) for several system functions. The ROM contains, primarily device initialization and security. ROM code is executed, in protection context '0'.
- **eFuse:** A one-time programmable (OTP) eFuse array consists of 1024 bits, which are reserved for system use such as Die ID, Device ID, initial trim settings, device life cycle, and security settings. Some of the bits are available for storing security key information and hash values and can be programmed by the user for device security. Each fuse is individually programmed; once programmed (or "blown"), its state cannot be changed. Blowing a fuse transitions it from the default state of '0' to '1'. To program an eFuse, VDDIO1 must be at 2.5 V $\pm$ 5%.

Because blowing an eFuse is an irreversible process, programming is recommended only in mass production under controlled factory conditions by Infineon provided provisioning tools.

- **8 Mb integrated flash:** CYW89829 has 8 Mb integrated flash for user applications. For more information, please see the [8 Mb integrated flash](#) section.

Functional description

2.1.12 Boot code

On a device reset, the boot code in ROM is the first code to execute. This code performs the following:

- Device trim setting (calibration)
- Setting the device protection units
- Setting device access restrictions for secure life cycle states
- Configures the Debug Access Port
- In secure life cycle supports secure debug via authenticated debug token
- In secure life cycle validates first user code in integrated flash by checking its digital signature. Supports OTF decryption of encrypted images in integrated flash
- Copies the application bootstrap from the integrated flash to SRAM and jumps to it ROM cannot be changed and acts as the Root of Trust in a secure system

It should also be noted that the ROM code sets the system clock to 48 MHz IHO source.

2.1.13 Memory map

The 32-bit (4 GB) address space is divided into the regions shown in [Table 3](#). Note that code can be executed from the Code, internal RAM, or integrated flash.

Table 2 Address map

Address range	Name	Use
0x0000 0000 – 0x1FFF FFFF	Code	Program code region. It includes the exception vector table, which starts at address 0
0x2000 0000 – 0x3FFF FFFF	SRAM	Data region
0x4000 0000 – 0x5FFF FFFF	Peripheral	All peripheral registers. Code cannot be executed from this region. Bit-band in this region is not supported
0x6000 0000 – 0x8FFF FFFF	8 Mb integrated flash	Quad SPI, (see the 8 Mb integrated flash section). The code can be executed from this region
0xA000 0000 – 0xDFFF FFFF	External Device	Not used
0xE000 0000 – 0xE00F FFFF	Private Peripheral Bus	Provides access to peripheral registers within the CPU core
0xE010 0000 – 0xFFFF FFFF	Device	Device-specific system registers

The device memory map is shown in [Table 3](#).

Table 3 Internal memory address map

Address range	Memory type	Size
0x0000 0000 – 0x0001 0000	ROM	64 KB
0x2000 0000 – 0x2004 0000	SRAM	Up to 256 KB

System resources

3 System resources

3.1 Power system

The power system provides assurance that voltage levels are as required for each respective mode and will either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (brownout detect (BOD)) when the power supply drops below specified levels. The design guarantees safe chip operation between power supply voltage dropping below specified levels (for example, below 2.7 V) and the reset occurring. There are no voltage sequencing requirements. CYW89829 does not support POR/BOD to guarantee EFUSE programming voltage.

Customer should use:

- External brownout detect (BOD), or internal voltage monitor functionality to verify supply voltage is at or above the flash operation voltage (2.7 V)^[2].

The VDDD supply (2.7 V to 3.6 V) powers an on-chip buck regulator which offers a selectable (1.0 V or 1.1 V) core operating voltage (VCCD). The selection lets users choose between two system power modes:

- System Low-Power (LP) operates VCCD at 1.1 V and offers high performance, with no restrictions on device configuration.
- System Ultra-Low-Power (ULP) operates VCCD at 1.0 V for exceptional low-power, but imposes limitations on clock speeds.

The Bluetooth® radio requires 1.1 V for operation. Bluetooth® system may override user core voltage selection when the radio is turned on. The system voltage will return to the user selected value automatically once Bluetooth® radio activity is completed. See [Power supply considerations](#) for more details.

3.1.1 Power modes

CYW89829 can operate in four system and three CPU power modes. These modes are intended to minimize the average power consumption in an application. For more details on power modes and other power-saving configuration options, see the relevant application note.

The power modes supported by CYW89829, in the order of decreasing power consumption, are:

- System Low-Power (LP) - All peripherals and CPU power modes are available at maximum speed
- System Ultra-Low-Power (ULP) - All peripherals and CPU power modes are available, but with limited speed
- CPU Active - CPU is executing code in system LP or ULP mode
- CPU Sleep - CPU code execution is halted in system LP or ULP mode
- CPU Deep Sleep - CPU code execution is halted and system Deep Sleep is requested in system LP or ULP mode
- System Deep Sleep - Only low-frequency peripherals are available after both CPUs enter CPU Deep Sleep mode
- Deep Sleep RAM - only RAM and IO states are retained. All system activity except for select low power peripherals ceases until system exits from this state. The CPU resets upon exit but can skip software initialization since RAM is retained.
- System Hibernate - Device and I/O states are frozen and the device resets on wakeup. Multiple sources available to wake up from this mode, including RTC, P0.5 and P1.4

The CPU Active, Sleep, and Deep Sleep are standard Arm®-defined power modes supported by the Arm® CPU instruction set architecture (ISA). System LP, ULP, Deep Sleep, Deep Sleep RAM, and Hibernate modes are additional low-power modes supported by the CYW89829.

Note

2. The internal voltage monitor serves as a software BOD with automatic wake up and voltage monitoring functionality within Active, Idle, and Sleep modes. For BOD functionality in Deep Sleep, Deep Sleep RAM, and Hibernate, an external brownout detect circuit is needed.

System resources

3.1.2 CYW89829 clock system

CYW89829 clock system consists of a combination of oscillators, external clock, and frequency-locked loop. Specifically, the following:

- Internal main oscillator (IMO)
- Internal low-speed oscillator (ILO)
- Watch crystal oscillator (WCO)
- System 24 MHz crystal oscillator
- External clock input
- One frequency-locked loop (FLL)
- Internal high-speed oscillator (IHO)

Clocks may be buffered and brought out to a pin on a smart I/O port.

Table 4 shows the mapping of port and associated clock group mapped to peripherals.

Table 4 Mapping of clock groups to peripherals

PCLK group	Root clock (clk_hf)	Peripherals	Frequency		Description
			LP (1.1 V typ)	ULP (1.0 V typ)	
0	clk_hf0	CPU Trace	24 MHz	24 MHz	–
1	clk_hf1	SCB	96 MHz	48 MHz	Async peripherals: Strobe signals are driven through dividers; Interface clock is generated inside the peripheral with the main group clock.
		TCPWM			
		LIN			
		CANFD			
		SMARTIO			
2	clk_hf0	BTSS	96 MHz	48 MHz	Direct connection pass through from clk_hf. This clock is not used for interface clock, rather it is used for the MMIO clocks of BTSS and CRYPTO. BTSS uses this clock for Master and Slave AHB/MMIO transactions.
		CRYPTO			
3	clk_hf1	PDM	96 MHz	48 MHz	Uses PERI ACLK with default div by 2 option, required interface frequencies are obtained by further division inside the peripheral.
		TDM			
4	clk_hf2	BTSS	48 MHz	48 MHz	RPU clock for BTSS
5	clk_hf3	ADCMIC	24 MHz	24 MHz	Direct connection for ADC, main source of clk_hf3 is clk_althf which is the BTSS ECO clock.

System resources

3.1.3 Internal main oscillator (IMO)

The IMO is the primary source of internal clocking. It is trimmed during testing to achieve the specified accuracy. The IMO default frequency is 8 MHz and tolerance is $\pm 2\%$.

3.1.4 Internal low-speed oscillator (ILO)

The ILO is a very low power oscillator, nominally 32 kHz, which operates in all power modes.

3.1.5 Precision internal low-speed oscillator (PILO)

The PILO is a precision low-power oscillator running at 32 kHz. It is factory calibrated to meet Bluetooth® Low Energy requirements. Like the ILO, it can operate in all power modes.

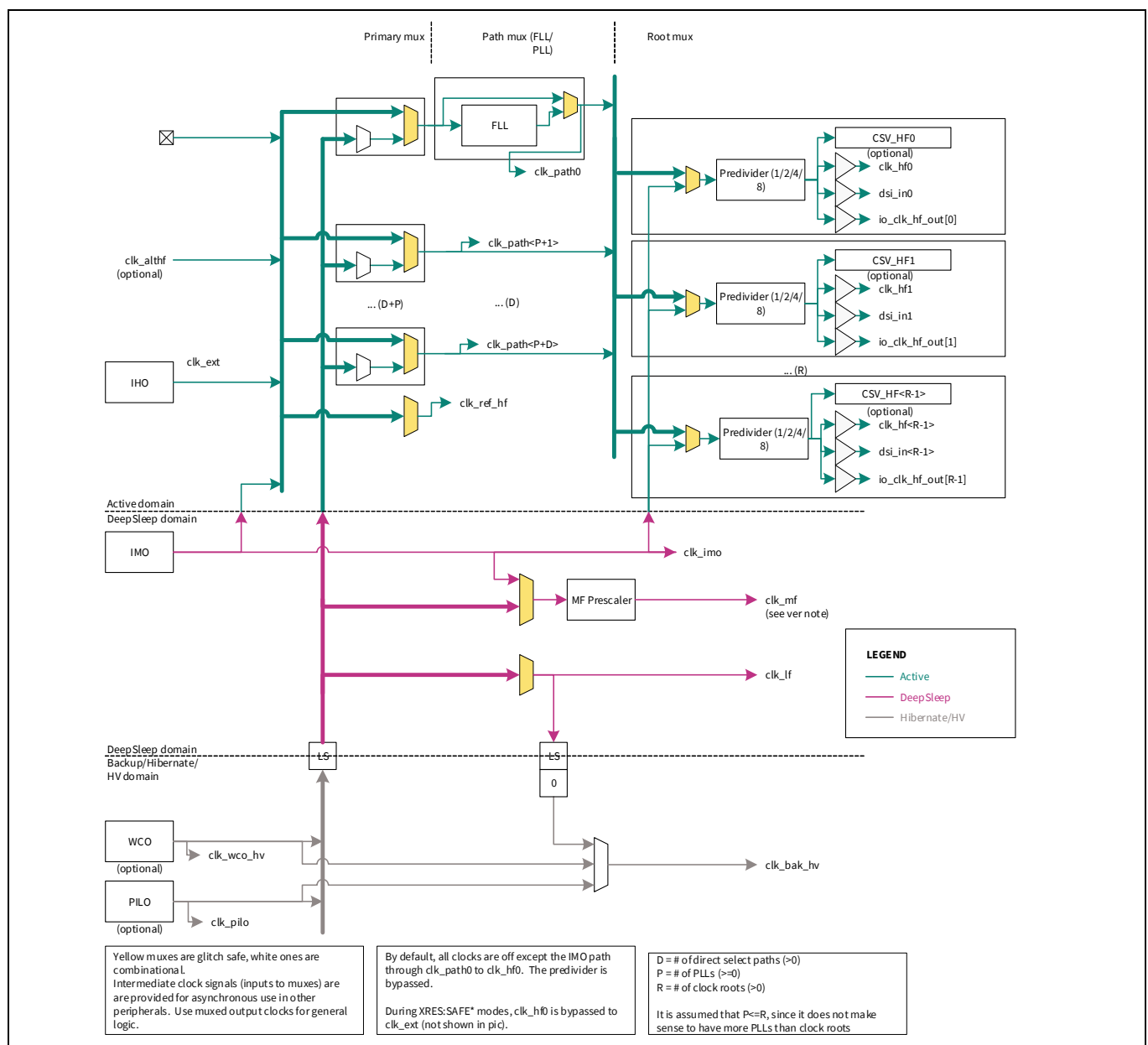


Figure 3 CYW89829 clocking diagram with corresponding oscillators

Note : Using PILO as the ILO clock source will result in longer boot time.

System resources

3.2 Main crystal oscillator

CYW89829 uses a 24 MHz crystal oscillator (XTAL).

The XTAL must have an accuracy as defined by the Bluetooth® specification. Two external load capacitors are required to work with the crystal oscillator. The selection of the load capacitors is XTAL-dependent (see [Figure 4](#)).

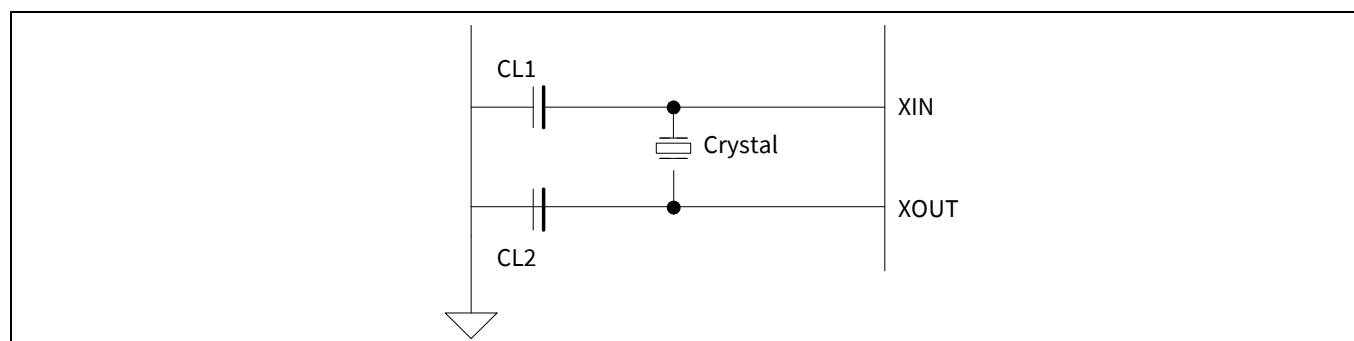


Figure 4 Recommended oscillator configuration

Table 5 Reference crystal electrical specifications

Parameter	Symbol	Electrical specification				Note
		Min	Typ	Max	Unit	
Nominal frequency	FL	24.00			MHz	–
Oscillation mode	–	Fundamental			–	–
Load capacitance	CL	8			pF	–
Frequency tolerance	–	±10			ppm	at 25°C ± 3°C
Frequency stability	–	± 20			ppm	Over operating temperature range (reference 25°C)
Operating temperature	–	–40	–	105	°C	–
Aging	–	±3			ppm	First year at 25°C ± 3°C
Drive level	DL	–	100	200	μW	–
Series resonant resistance	Rr	–	–	60	Ω	–
Shunt capacitance	C0	–	–	3	pF	–
Insulation resistance	–	500	–	–	MΩ	at DC 100 V
Storage temperature range	–	–40	–	125	°C	–

System resources

3.3 32 kHz crystal oscillator

CYW89829 includes a 32 kHz oscillator to provide accurate timing during low power operations. **Figure 5** shows the 32 kHz XTAL oscillator with external components and **Table 6** lists the oscillator's characteristics. This oscillator can be operated with a 32 kHz or 32.768 kHz crystal oscillator or be driven with a clock input at similar frequency. The XTAL must have an accuracy of ± 250 ppm or better per the Bluetooth® spec over temperature and including aging. The default component values are: $C1 = C2 = \sim 6$ pF. The values of C1 and C2 are used to fine-tune the oscillator.

Note : The 32.768 kHz crystal is optional and may be omitted. CYW89829 has an internal PILO (precision internal low-speed oscillator).

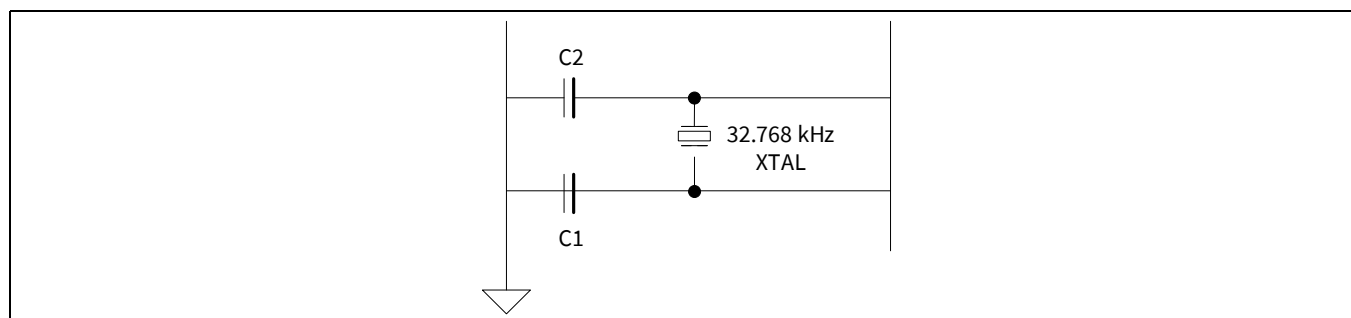


Figure 5 32 kHz oscillator block diagram

Table 6 XTAL oscillator characteristics

Parameter	Sym	Conditions	Min	Typ	Max	Unit
Output frequency	F_{oscout}	–	–	32.768	–	kHz
Frequency tolerance	–	Over temperature and aging	–	–	250	ppm
XATL driver level	P_{drv}	For crystal selection	–	0.1	0.5	μW
XTAL series resistance	R_{series}	For crystal selection	–	–	70	$K\Omega$
XATL shunt capacitance	C_{shunt}	For crystal selection	–	–	2.2	pF

3.3.1 Watchdog timers (WDT, MCWDT)

CYW89829 has one WDT and two multi-counter WDTs (MCWDTs). The WDT has a 16-bit free-running counter. Each MCWDT has two 16-bit counters and one 32-bit counter, with multiple operating modes. All of the 16-bit counters can generate a watchdog device reset. All of the counters can generate an interrupt on a match event.

The WDT is clocked by the ILO. It can do interrupt/wakeup generation in system LP/ULP, Deep Sleep, and Hibernate power modes. The MCWDTs are clocked by LFCLK (ILO or WCO). It can do periodic interrupt/wakeup generation in system LP/ULP and Deep Sleep power modes.

3.3.2 Clock dividers

Integer and fractional clock dividers are provided for peripheral use and timing purposes. There are one or more:

- 8-bit clock dividers
- 16-bit integer clock dividers
- 16.5-bit fractional clock dividers
- 24.5-bit fractional clock divider

System resources

3.3.3 Trigger routing

CYW89829 contains a trigger multiplexer block. This is a collection of digital multiplexers and switches that are used for routing trigger signals between peripheral blocks and between GPIOs and peripheral blocks.

There are two types of trigger routing. Trigger multiplexers have reconfigurability in the source and destination. There are also hardwired switches called “one-to-one triggers”, which connect a specific source to a destination. The user can enable or disable the route.

3.3.4 Reset

CYW89829 can be reset from a variety of sources:

- Power-on reset (POR) to hold the device in reset while the power supply ramps up to the level required for the device to function properly. POR activates automatically at power-up.
- Brown-out detect (BOD) reset to monitor the digital voltage supply VDDD and generate a reset if VDDD falls below the minimum required logic operating voltage.
- External reset dedicated pin (XRES) to reset the device using an external source. The XRES pin is active LOW. It can be connected either to a pull-up resistor to VDDD, or to an active drive circuit, as [Figure 6](#) shows. If a pull-up resistor is used, select its value to minimize current draw when the pin is pulled LOW; 10 kΩ is typical.

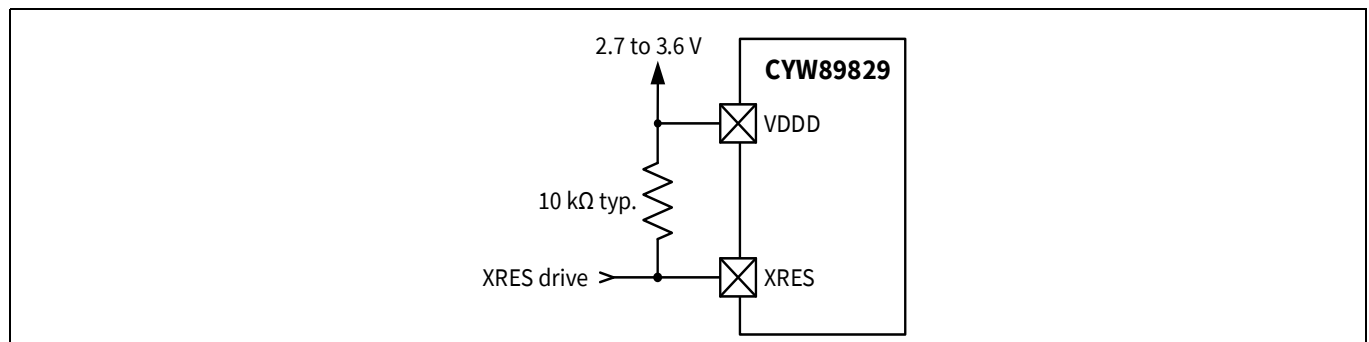


Figure 6 XRES connection diagram

- Watchdog timer (WDT or MCWDT) to reset the device if firmware fails to service it within a specified timeout period.
- Software-initiated reset to reset the device on demand using firmware.
- Logic-protection fault can trigger an interrupt or reset the device if unauthorized operating conditions occur; for example, reaching a debug breakpoint while executing privileged code.
- Hibernate wakeup reset to bring the device out of the system Hibernate low-power mode.

The reset events are asynchronous and guarantee reversion to a known state. Some of the reset sources are recorded in a register, which is retained through reset and allows software to determine the cause of the reset.

3.4 Bluetooth® LE radio and subsystem

CYW89829 incorporates a Bluetooth® 5.4 LE subsystem (BLESS) that contains the physical layer (PHY) and link layer (LL) engines with an embedded security engine. The Bluetooth® LE SS supports all Bluetooth® LE 5.4 features including LE 2 Mbps, LE Long Range, LE Advertising Extensions, LE Isochronous Channels, Periodic Advertising with Responses (PAwR), Encrypted Advertising Data, LE GATT Security Levels Characteristic and

System resources

Advertising Coding Selection. Infineon also provides extensive driver library and middleware support for Bluetooth® LE; see [“Eclipse IDE for Modustoolbox™ software”](#) on page 4.

The physical layer consists of the digital PHY and the RF transceiver that transmits and receives Gaussian frequency shift keying (GFSK) packets at 1 or 2 Mbps over a 2.4 GHz ISM band. The device also supports Bluetooth® LE long range, both 500 and 125 kbps speeds.

The baseband controller is a composite hardware and firmware implementation that supports both Master and Slave modes. The key protocol elements, such as HCI and link control, are implemented in firmware. The Time-critical functional blocks, such as encryption, CRC, data whitening, and access code correlation, are implemented in hardware (in the LL engine).

The RF transceiver contains an integrated balun, which provides a single-ended RF port pin to drive a 50 Ω antenna via a matching/filtering network. In the receive direction, this block converts the RF signal from the antenna to a digital bit stream after performing GFSK demodulation. In the transmit direction, this block performs GFSK modulation and then converts a digital baseband signal to a radio frequency before transmitting it through the antenna.

3.5 Programmable analog-to-digital converter (ADC)

3.5.1 Sigma-delta ADC

The ADC block is a single switched-cap Σ - Δ ADC core for audio and DC measurement. It operates at the 12 MHz clock rate and has eight GPIO inputs. The internal bandgap reference has $\pm 5\%$ accuracy without calibration. Different calibration and digital correction schemes can be applied to reduce ADC absolute error and improve measurement accuracy in DC.

One of three internal references may be used for the ADC reference voltage: ACD_VDD, ACD_VDD/2, and an analog reference (AREF). AREF is nominally 1.2 V, trimmed to $\pm 1\%$.

3.6 Programmable digital

- System Deep Sleep operation
- Asynchronous or synchronous (clocked) operation
- Can be synchronous or asynchronous

System resources

3.7 Fixed-function digital

3.7.1 Timer/counter/pulse-width modulator (TCPWM) block

- The TCPWM supports the following operational modes:
 - Timer-counter with compare
 - Timer-counter with capture
 - Pulse width modulation (PWM)
 - Pseudo-random PWM
 - PWM with dead time
- Up, down, and up/down counting modes
- Clock pre-scaling (division by 1, 2, 4, ... 64, 128)
- Double buffering of compare/capture and period values
- Underflow, overflow, and capture/compare output signals
- Supports interrupt ON:
 - Terminal count - Depends on the mode; typically occurs on overflow or underflow
 - Capture/compare - The count is captured to the capture register or the counter value equals the value in the compare register
- Complementary output for PWMs
- Selectable start, reload, stop, count, and capture event signals for each TCPWM; with rising edge, falling edge, both edges, and level trigger options. The TCPWM has a Kill input to force outputs to a predetermined state.

In this device there are:

- Two 32-bit TCPWMs
- Seven 16-bit TCPWMs

3.7.2 Serial communication blocks (SCB)

- This product line has three SCBs:
 - First SCB: configurable as SPI or I²C
 - Second SCB: configurable as SPI or UART
 - Third SCB: configurable as I²C or UART

Note : Only one of the protocols is supported by an SCB at any given time. In addition, all three SCBs can be configured for I²C or SPI to use at the same time. However, only two SCBs can be configured for UART to use at the same time.

- One SCB (SCB #0) can operate in system Deep Sleep mode with an external clock; this SCB can be either SPI slave or I²C slave.
- **I²C mode**: The SCB can implement a full multi-master and slave interface (it is capable of multimaster arbitration). This block can operate at speeds of up to 1 Mbps (Fast Mode Plus). It also supports EZI²C, which creates a mailbox address range and effectively reduces I²C communication to reading from and writing to an array in the memory. The SCB supports a 256-byte FIFO for receive and transmit. The I²C peripheral is compatible with I²C standard-mode, Fast mode, and Fast mode Plus devices. The I²C bus I/O is implemented with GPIO in open-drain modes.
- **UART mode**: This is a full feature UART operating at up to 8 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO 7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit Multiprocessor mode that allows the addressing of peripherals connected over common Rx and Tx lines. Common UART functions such as parity error, break detect, and frame error are supported. A 256 byte FIFO allows much greater CPU service latencies to be tolerated.

System resources

- **SPI mode:** The SPI mode supports full SPI, Secure Simple Pairing (SSP) (essentially adds a start pulse that is used to synchronize SPI Coders), and Microwire (half-duplex form of SPI). The SPI block supports an EZSPI mode in which the data interchange is reduced to reading and writing an array in memory. The SPI interface operates with a 24 MHz clock.

3.7.3 8 Mb integrated flash

An 8 Mb integrated flash is provided, running at up to 48 MHz. It supports:

- Execute-in-place (XIP), in which AHB reads and writes are directly translated to SPI read and write transfers.

In XIP mode, the integrated memory is mapped into the CYW89829 internal address space, enabling code execution directly from the integrated memory. To improve performance, a 32 KB cache is included. The XIP mode also supports AES-128 based on-the-fly encryption and decryption, enabling secure storage and access of code and data in the integrated memory.

The 8 Mb integrated flash has more than 100,000 erase/write cycles, and more than 20 year data retention.

3.8 GPIO

CYW89829 has up to 26 GPIOs, which implement:

- Eight drive strength modes:
 - Analog input mode (input and output buffers disabled) on some IOs
 - Input only
 - Weak Pull-up with Strong Pull-down
 - Strong Pull-up with Weak Pull-down
 - Open Drain with Strong Pull-down
 - Open Drain with Strong Pull-up
 - Strong Pull-up with Strong Pull-down
 - Weak Pull-up with Weak Pull-down
 - Hold mode for latching previous state (used for retaining the I/O state in system Hibernate and Deep Sleep mode)
 - Selectable slew rates for dV/dt-related noise control to improve EMI

The pins are organized in logical entities called ports, which are up to eight pins in width. The data output and pin state registers store, respectively, the values to be driven on the pins and the input states of the pins.

Every pin generates an interrupt if enabled; each port has an interrupt request (IRQ) associated with it.

The port 4 pins are capable of overvoltage-tolerant (OVT) operation, where the input voltage may be higher than VDDD. OVT pins are commonly used with I²C, to allow powering the chip OFF while maintaining a physical connection to an operating I²C bus without affecting its functionality.

The GPIO pins can be ganged to source or sink higher values of current. GPIO pins, including OVT pins, may not be pulled up higher than the absolute maximum; see **“Electrical specifications”** on page 30.

During power-on and reset, the pins are forced to the analog input drive mode, with input and output buffers disabled, so as not to crowbar any inputs and/or cause excess turn-on current.

A multiplexing network known as the high-speed I/O matrix (HSIOM) is used to multiplex between various peripheral and analog signals that may connect to an I/O pin.

In order to get the best performance, the following frequency and drive mode constraints may be applied. The DRIVE_SEL values (see **Table 7**) represent drive strengths.

Table 7 DRIVE_SEL values

Ports	Maximum frequency	Drive strength for VDDD = 2.7 V	Drive strength for VDDD > 2.7 V
Ports 0, 1	8 MHz	Up to 4 mA	Up to 8 mA
Ports 2 to 5	16 MHz; 24 MHz for SPI	Up to 4 mA	Up to 8 mA

3.9 Special function peripherals

3.9.1 Audio subsystem

This subsystem consists of the following hardware blocks:

- One inter-IC sound (I²S) interface
 - Two pulse-density modulation (PDM) to pulse-code modulation (PCM) decoder channels
- The I²S interface implements two independent hardware FIFO buffers - TX and RX, which can operate in master or slave mode. The following features are supported:

- Multiple data formats - I²S, left-justified, Time Division Multiplexed (TDM) mode A, and TDM mode B
- Programmable channel/word lengths - 8/16/18/20/24/32 bits
- Internal/external clock operation. Up to 192 ksp/s
- Interrupt mask events - trigger, not empty, full, overflow, underflow, watchdog
- Configurable FIFO trigger level with datawire support

The I²S interface is commonly used to connect with audio codecs, simple DACs, and digital microphones. The PDM-to-PCM decoder implements a single hardware Rx FIFO that decodes a stereo or mono 1-bit PDM input stream to PCM data output. The following features are supported:

- Configurable PDM clock generation. Range from 384 kHz to 3.072 MHz
- Programmable data output word length - 16/18/20/24 bits
- Droop correction and configurable decimation rate for sampling; up to 48 ksp/s
- Programmable high-pass filter gain
- Interrupt mask events - not empty, overflow, trigger, underflow
- Configurable FIFO trigger level with DMA support

The PDM-to-PCM decoder is commonly used to connect to digital PDM microphones. Up to two microphones can be connected to the same PDM data line.

Pinouts

4 Pinouts

Table 8 Packages and pin information

Pin name	Pin number BGA-77	I/O	Power domain	Description
Microphone				
MIC_P	C9	I	ADC_VDD	Microphone positive input
MIC_N	B9			Microphone negative input
MIC_BIAS	D9	O		Microphone bias supply
Onboard switching regulator and LDOs				
VDDQ	C3	I	–	External supply to PMU analog
VCC_BUCK	A6		–	External supply to switching regulator
LX_BUCK	A4	O	–	Switching regulator output
VCCD	B2		–	Digital LDO output
VCCI	A3	I	–	RF and digital LDO input
Baseband supply				
VDDIO_0	H8	I	VDDIO_0	Supply for GPIO ports
VDDIO_1	G10		VDDIO_1	Supply for GPIO ports and eFuse programming. See Table 11 for eFuse programming requirements.
VDDIO_A	A7		VDDIO_A	Supply for analog GPIO ports
ADC_VDD	C10		ADC_VDD	Analog power supply voltage
VCC	F10		VCC	Supply for integrated flash
RF power supply				
VCCRF	A2	O	–	RFLDO output
VDDD	B1	I	–	PALDO and subsystem resources supply
VCCPA	C1	O	–	PALDO output
BT_VCOVDD	G2	I	BT_VCOVDD	VCO supply
BT_LNAVDD	G1		BT_LNAVDD	LNA supply
BT_IFVDD	D2		BT_IFVDD	IFPLL power supply
BT_PLLVDD	H2		BT_PLLVDD	RFPLL and crystal oscillator supply
BT_PAVDD	D1		BT_PAVDD	Internal PA supply
Ground pins				
ADC_VSS	B10	–	AVSS	Analog Ground
VSS	D5	–	VSS	Ground
VSS	D4	–	VSS	Ground
VSS	G4	–	VSS	Ground
VSS	B6	–	VSS	Ground
VSS	F5	–	VSS	Ground
VSS	D10	–	VSS	Ground
VSS0	H9	–	VSS0	Ground
VSSBUCK	A5	–	VSSBUCK	Ground
VSS	B3	–	VSS	Ground

Pinouts

Table 8 Packages and pin information (continued)

Pin name	Pin number	I/O	Power domain	Description
	BGA-77			
IFVSS	E2	–	IFVSS	Ground
PLLVSS	G3	–	PLLVSS	Ground
VCOVSS	F3	–	VCOVSS	Ground
LNAVSS	F2	–	LNAVSS	Ground
PAVSS	F1	–	PAVSS	Ground
VSS	D3	–	VSS	Ground

Radio I/O

BT_RF	E1	I/O	BT_RF	RF antenna port
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Crystal

BT_XTALI	H3	I	BT_PLLVDD	Crystal oscillator input. Two external load capacitors are required to work with the crystal oscillator. The selection of the load capacitors is XTAL-dependent.
BT_XTALO	H4	O		Crystal oscillator output

Reserved

RSVD0	G9	–	–	Connect a 10 kΩ pull up resistor to VDDIO
RSVD1	F9	–	–	Leave unconnected
RSVD2	E8	–	–	Leave unconnected
RSVD3	E10	–	–	Leave unconnected
RSVD4	E9	–	–	Leave unconnected
RSVD5	D8	–	–	Leave unconnected
NC_0	A1	–	–	Leave unconnected
NC_1	A10	–	–	Leave unconnected
NC_2	H1	–	–	Leave unconnected
NC_3	H10	–	–	Leave unconnected

Pinouts

Table 8 Packages and pin information *(continued)*

Pin name	Pin number	I/O	Power domain	Description
	BGA-77			
GPIO				
P0.0	H5	I/O	VDDIO	General input and output port. See Table 9 for alternate functions.
P0.1	G5			
P0.2	E5			
P0.3	E6			
P0.4	F6			
P0.5	G6			
P1.0	H6			
P1.1	H7			
P1.2	G7			
P1.3	F7			
P1.4	E7			
P1.5	F8			
P1.6	G8			
P3.0	B8			
P3.1	C8			
P3.2	D7			
P3.3	B7			
P3.4	C7			
P3.5	C6			
P3.6	D6			
P3.7	C5			
P4.0	C4			
P4.1	B4			
P5.0/ WCO_OUT	A9			
P5.1/WCO_IN	A8			
P5.2	B5			
XRES	E3	I	–	Active LOW system reset without internal pull-up resistor



Pinouts

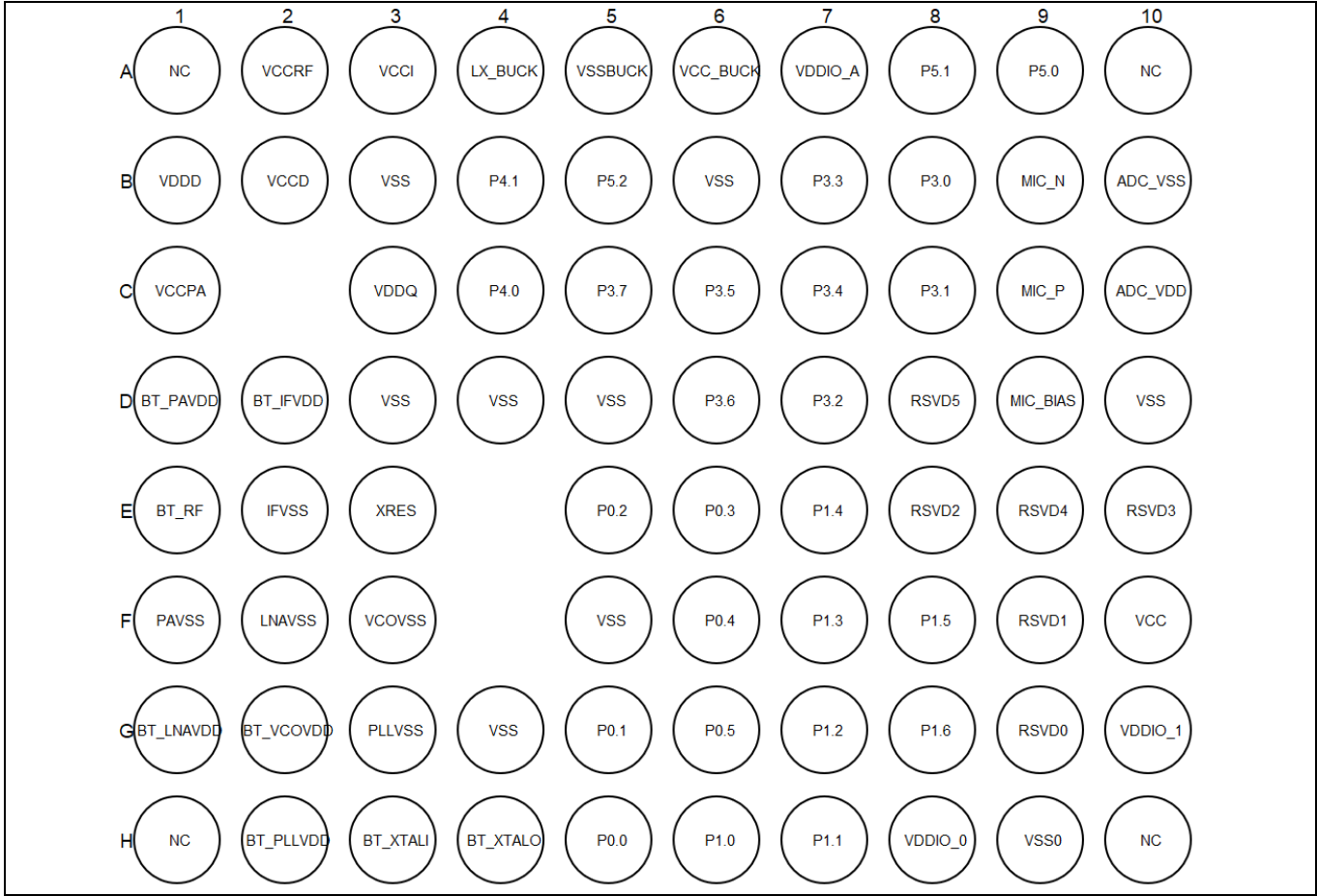


Figure 7 Device pinout for 77-ball BGA package

Each port pin has multiple alternate functions. These are defined in [Table 9](#).

Pinouts

Table 9 Multiple alternate functions^[3]

Port/ Pin	Analog	ACT #0	ACT #1	ACT #2	ACT #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #11	ACT #12	ACT #13	ACT #15	DS #2	DS #3	DS #5	DS #6
P0.0	–	tcpwm[0].line_compl[0]:3	tcpwm[0].line_compl[262]:0	–	–	–	–	–	–	–	pdm.pdm_clk[1]:0	–	tadm.tadm_rx_mck[0]:0	–	–	keyscan.ks_col[3]	–	–	scb[0].spi_select1:0
P0.1	–	tcpwm[0].line[1]:3	tcpwm[0].line[256]:1	–	–	–	–	–	–	–	pdm.pdm_data[1]:0	–	tadm.tadm_rx_sck[0]:0	–	–	keyscan.ks_col[4]	–	–	scb[0].spi_select2:0
P0.2	–	tcpwm[0].line_compl[1]:3	tcpwm[0].line_compl[256]:1	–	–	–	–	–	–	–	–	–	tadm.tadm_rx_fs_ync[0]:0	–	–	keyscan.ks_col[11]	scb[0].i2c_scl:0	–	scb[0].spi_mosi:0
P0.3	–	tcpwm[0].line[0]:4	tcpwm[0].line[257]:1	–	–	–	–	–	–	scb[1].spi_select3:0	–	–	tadm.tadm_rx_sd[0]:0	–	–	keyscan.ks_col[12]	scb[0].i2c_sda:0	–	scb[0].spi_miso:0
P0.4	–	tcpwm[0].line_compl[0]:4	tcpwm[0].line_compl[257]:1	–	–	srss.ext_clk:0	cpuss.trace_data[3]:1	–	–	scb[1].spi_select2:0	–	–	tadm.tadm_tx_mck[0]:0	–	–	keyscan.ks_row[0]	–	–	scb[0].spi_clk:0

Note

3. The notation for a signal is of the form IPName[x].signal_name[u]:y. IPName = Name of the block (such as tcpwm), x = Unique instance of the IP, Signal_name = Name of the signal, u = Signal number where there are more than one signals for a particular signal name, y = Designates copies of the signal name. For example, the name tcpwm[0].line_compl[3]:4 indicates that this is instance 0 of a tcpwm block, the signal is line_compl # 3 (complement of the line output) and this is the fourth occurrence (copy) of the signal. Signal copies are provided to allow flexibility in routing and to maximize utilization of on-chip resources.

P0.5	–	tcpwm[0].line[1]:4	tcpwm[0].line[258]:1	btss.antenna_switch_ctrl[0]	–	–	cpuss.trace_data[2]:1	–	–	scb[1].spi_select1:0	–	–	tadm.tadm_tx_sck[0]:0	btss.gci_gpio[0]	–	keyscan.ks_row[1]	–	–	–
P1.0	–	tcpwm[0].line_compl[1]:4	tcpwm[0].line_compl[258]:1	btss.antenna_switch_ctrl[1]	btss.rpu_tdo	–	cpuss.trace_data[1]:1	scb[1].uart_cts:0	–	scb[1].spi_select0:0	pdm.pdm_clk[1]:1	–	tadm.tadm_tx_fs_ync[0]:0	btss.gci_gpio[1]	–	keyscan.ks_row[5]	–	cpuss.swj_sw_tdo	–
P1.1	–	tcpwm[0].line[0]:5	tcpwm[0].line[259]:1	btss.antenna_switch_ctrl[2]	btss.rpu_tdi	–	cpuss.trace_data[0]:1	scb[1].uart_rts:0	–	scb[1].spi_clk:0	pdm.pdm_data[1]:1	–	tadm.tadm_tx_sd[0]:0	btss.gci_gpio[2]:0	–	keyscan.ks_row[6]	–	cpuss.swj_sw_tdi	–
P1.2	–	tcpwm[0].line_compl[0]:5	tcpwm[0].line_compl[259]:1	–	btss.rpu_swd	–	cpuss.trace_clock:1	scb[1].uart_rx:0	scb[2].i2c_scl:1	scb[1].spi_mosi:0	–	–	–	btss.gci_gpio[3]	–	–	keyscan.ks_col[17]:0	cpuss.swj_sw_tms	–
P1.3	–	tcpwm[0].line[1]:5	tcpwm[0].line[260]:1	–	btss.rpu_tck	srss.ext_clk:1	–	scb[1].uart_tx:0	scb[2].i2c_sda:1	scb[1].spi_miso:0	–	–	–	btss.gci_gpio[4]	–	–	keyscan.ks_col[16]:0	cpuss.clk_swj_sclk_tclk	–
P1.4	–	tcpwm[0].line_compl[1]:5	tcpwm[0].line_compl[260]:1	–	–	–	–	–	–	–	–	lin[0].lin_en[1]:0	–	btss.gci_gpio[2]:1	–	keyscan.ks_col[15]	keyscan.ks_col[16]:1	–	–

Table 9 Multiple alternate functions^[3] (continued)

Port/ Pin	Analog	ACT #0	ACT #1	ACT#2	ACT#3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #11	ACT #12	ACT #13	ACT #15	DS #2	DS #3	DS #5	DS #6
P1.5	–	tcpwm[0].line[0]:6	tcpwm[0].line[261]:1	–	–	–	–	–	–	–	–	lin[0].lin_rx[1]:0	–	–	–	keyscan.ks_col[5]	–	–	–
P1.6	–	tcpwm[0].line_compl[0]:6	tcpwm[0].line_compl[261]:1	–	–	–	–	–	–	–	–	lin[0].lin_tx[1]:0	–	–	–	keyscan.ks_col[6]	srss.cal_wave	–	–
P3.0	adcmic.gpio_adc_in[0]	tcpwm[0].line[0]:0	tcpwm[0].line[256]:0	–	–	–	cpuss.trace_data[3]:0	scb[2].uart_cts:0	–	scb[1].spi_select0:1	–	–	–	–	–	keyscan.ks_row[7]	–	–	–
P3.1	adcmic.gpio_adc_in[1]	tcpwm[0].line_compl[0]:0	tcpwm[0].line_compl[256]:0	–	–	–	cpuss.trace_data[2]:0	scb[2].uart_rts:0	–	scb[1].spi_clk:1	–	lin[0].lin_en[0]:0	–	–	btss.sys_clk_rf	keyscan.ks_row[4]	–	cpuss.rst_swj_trstn	–
P3.2	adcmic.gpio_adc_in[2]	tcpwm[0].line[1]:0	tcpwm[0].line[257]:0	–	–	–	cpuss.trace_data[1]:0	scb[2].uart_rx:0	scb[2].i2c_scl:0	scb[1].spi_mosi:1	pdm.pdm_clk[0]:0	lin[0].lin_rx[0]:0	canfd[0].ttcan_rx[0]:0	adcmic.clk_pdm:0	–	keyscan.ks_col[13]	–	–	–
P3.3	adcmic.gpio_adc_in[3]	tcpwm[0].line_compl[1]:0	tcpwm[0].line_compl[257]:0	–	–	–	cpuss.trace_data[0]:0	scb[2].uart_tx:0	scb[2].i2c_sda:0	scb[1].spi_miso:1	pdm.pdm_data[0]:0	lin[0].lin_tx[0]:0	canfd[0].ttcan_tx[0]:0	adcmic.pdm_data:0	–	keyscan.ks_col[14]	keyscan.ks_col[17]:1	–	–
P3.4	adcmic.gpio_adc_in[4]	tcpwm[0].line[0]:1	tcpwm[0].line[258]:0	–	–	–	cpuss.trace_clock:0	–	–	scb[1].spi_select3:1	–	–	–	–	–	keyscan.ks_col[7]	–	–	–
P3.5	adcmic.gpio_adc_in[5]	tcpwm[0].line_compl[0]:1	tcpwm[0].line_compl[258]:0	–	–	–	–	–	–	scb[1].spi_select2:1	–	–	–	–	–	keyscan.ks_col[8]	–	–	–
P3.6	adcmic.gpio_adc_in[6]	tcpwm[0].line[1]:1	tcpwm[0].line[259]:0	–	–	–	–	–	–	scb[1].spi_select1:1	–	–	–	–	–	keyscan.ks_col[9]	–	–	–
P3.7	adcmic.gpio_adc_in[7]	tcpwm[0].line_compl[1]:1	tcpwm[0].line_compl[259]:0	btss.antenna_switch_ctrl[3]	–	–	–	–	–	–	–	–	–	–	–	keyscan.ks_col[10]	–	–	–
P4.0	–	tcpwm[0].line_compl[1]:2	tcpwm[0].line_compl[261]:0	–	–	–	–	scb[2].uart_cts:2	–	–	–	–	–	–	–	keyscan.ks_row[2]	scb[0].i2c_scl:1	–	scb[0].spi_mosi:1
P4.1	–	tcpwm[0].line[0]:3	tcpwm[0].line[262]:0	–	–	–	–	–	–	–	–	–	–	–	–	keyscan.ks_row[3]	scb[0].i2c_sda:1	–	scb[0].spi_miso:1

Note

3. The notation for a signal is of the form IPName[x].signal_name[u]:y. IPName = Name of the block (such as tcpwm), x = Unique instance of the IP, Signal_name = Name of the signal, u = Signal number where there are more than one signals for a particular signal name, y = Designates copies of the signal name. For example, the name tcpwm[0].line_compl[3]:4 indicates that this is instance 0 of a tcpwm block, the signal is line_compl # 3 (complement of the line output) and this is the fourth occurrence (copy) of the signal. Signal copies are provided to allow flexibility in routing and to maximize utilization of on-chip resources.

Table 9 Multiple alternate functions^[3] (continued)

Port/ Pin	Analog	ACT #0	ACT #1	ACT#2	ACT#3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #11	ACT #12	ACT #13	ACT #15	DS #2	DS #3	DS #5	DS #6
P5.0	srss.wc o_in	tcpwm[0].line[0]:2	tcpwm[0].line[260]:0	–	–	–	–	scb[2].uart_cts:1	scb[2].i2c_scl:2	scb[1].spi_select0:2	pdm.pdm_clk[0]:1	–	canfd[0].ttcan_rx[0]:1	adcmic.clk_pdm:1	–	keyscan.ks_col[0]	–	–	–
P5.1	srss.wc o_out	tcpwm[0].line_compl[0]:2	tcpwm[0].line_compl[260]:0	–	–	–	–	–	scb[2].i2c_sda:2	–	pdm.pdm_data[0]:1	–	canfd[0].ttcan_tx[0]:1	adcmic.pdm_data:1	–	keyscan.ks_col[1]	–	–	scb[0].spi_select0:0
P5.2	–	tcpwm[0].line[1]:2	tcpwm[0].line[261]:0	–	–	–	–	–	–	–	–	–	–	–	–	keyscan.ks_col[2]	–	–	–

Note

- The notation for a signal is of the form IPName[x].signal_name[u]:y. IPName = Name of the block (such as tcpwm), x = Unique instance of the IP, Signal_name = Name of the signal, u = Signal number where there are more than one signals for a particular signal name, y = Designates copies of the signal name. For example, the name tcpwm[0].line_compl[3]:4 indicates that this is instance 0 of a tcpwm block, the signal is line_compl # 3 (complement of the line output) and this is the fourth occurrence (copy) of the signal. Signal copies are provided to allow flexibility in routing and to maximize utilization of on-chip resources.

Power supply considerations

5 Power supply considerations

Figure 8 shows the typical connections for power pins for all supported packages and it refers to 10 dBm PA configuration. For 0 dBm, connect BT_PAVDD to VCCRF.

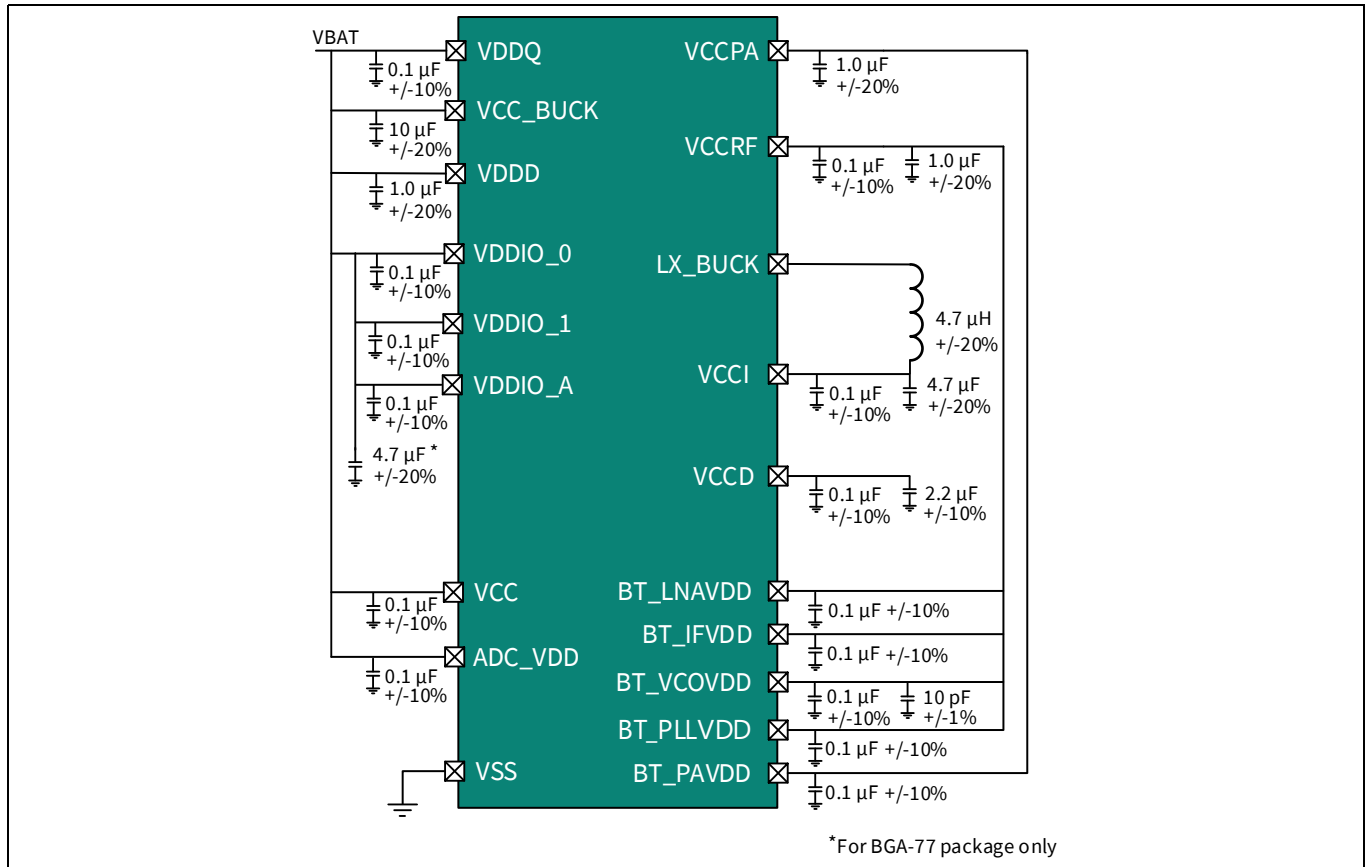


Figure 8 CYW89829 power topology

Electrical specifications

6 Electrical specifications

All specifications are valid for $-40^{\circ}\text{C} < T_A < 105^{\circ}\text{C}$ and for VDDD 2.7 V to 3.6 V except where noted.

6.1 Absolute maximum ratings

Table 10 Absolute maximum ratings^[4]

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID1	VDD_ABS	Analog or digital supply relative to V _{SS} (V _{SSD} = V _{SSA})	−0.5	−	4	V	Absolute maximum
SID2	VCCD_ABS	Direct digital core voltage input relative to V _{SSD}	−0.5		1.2		Absolute maximum
SID3	V _{GPIO_ABS}	GPIO voltage; VDDD or ADC_VDD	−0.5		VDDIO + 0.5		
SID4	I _{GPIO_ABS}	Current per GPIO	−25		25	mA	
SID5	I _{GPIO_injection}	GPIO injection current per pin	−0.5		0.5		
SID3A	ESD_HBM	Electrostatic discharge human body model	2200		−	V	
SID4A	ESD_CDM	Electrostatic discharge charged device model	500				
SID5A	LU	Pin current for latchup-free operation	−100		100	mA	
SIDWA8	V _{undershoot}	Maximum undershoot voltage for I/O	−		−0.5	V	Duration not to exceed 25% of the duty cycle
SIDWA9	V _{overshoot}	Maximum overshoot voltage for I/O			VDDIO + 0.5		
SIDWA10	T _j	Maximum junction temperature			125	°C	−

Note

4. Usage above the absolute maximum conditions listed in [Table 10](#) may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150°C in compliance with JEDEC Standard JESD22-A103, high temperature storage life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

Electrical specifications

6.2 Operating conditions

Table 11 Power supply range, CPU current, and transition time specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
DC specifications							
SID6	VDDD	Internal regulator	2.7	-	3.6	V	-
SID7	ADC_VDD	Analog power supply voltage. Shorted to VDDIO_A on PCB.	2.7	-	3.6	V	Internally unregulated supply
SID7M	MIC_BIAS	Microphone supply voltage					
SID7R	VCCI	RF/Digital LDO input. Connect to output of internal buck	-	1.16	-	-	-
SID7C							
SID7P	VDDD	PA LDO input	2.7	-	3.6	V	For TX10 mode, BT_PAVDD connected to VCCPA. The minimum supply voltage VDDD is 2.7 V
SID7F	VCC	Integrated flash supply	2.7		3.6	V	-
SID7B	VDDIO_0	GPIO supply for ports	2.7		3.6	V	-
SID7E	VDDIO_1	Supply when programming eFuse	2.38	2.5	2.62	V	eFuse programming voltage is 2.5 V +/- 5%
SID7A	VDDIO_A	GPIO supply for analog ports. Short to ADC_VDD on PCB	2.7		3.6	V	-
SID8	VCCD (LP)	Output voltage (for core logic bypass)	-	1.1	-	V	High-speed mode
SID9	VCCD (ULP)	Output voltage (for core logic bypass)		1.0			ULP mode. Valid for -40°C to 105°C
SID10	C_EFC	External regulator voltage (VCCD) bypass	3.8	4.7	5.6	μF	X6S ceramic or better. Value for 0.8 V to 1.2 V
SID11	C_EXC	Power supply decoupling capacitor	-	10	-		X6S ceramic or better
SID12	VCCRF	Output voltage (for radio)	-	1.1	-	V	-
SID13	VCCPA	Output voltage (for PA)		2.5			
SID523	VDDQ	External supply to PMU analog	2.7	-	3.6		
SID524	VCC_BUCK	External supply to switching regulator			2.75		
SID525	BT_PAVDD	Internal PA supply	1		1.2		
SID526	BT_RF	RF power supply					
SID527	BT_LNAVDD	LNA supply					
SID528	BT_IFVDD	IFPLL power supply					
SID529	BT_VCOVDD	VCO supply					

Note

5. Usage above the absolute maximum conditions listed in [Table 10](#) may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150°C in compliance with JEDEC Standard JESD22-A103, high temperature storage life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

Electrical specifications

Table 11 Power supply range, CPU current, and transition time specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
CPU currents and transition times Cortex® M33 Active mode							
Execute with cache enabled							
SIDC2	I _{DD4}	Execute from cache; CM33 Active 96 MHz. FLL. Dhrystone	–	4.8	5.8	mA	VDDD = 3.0 V, buck ON, Max at 60°C
SIDC3	I _{DD5}	Execute from cache; CM33 Active 48 MHz. IHO. Dhrystone	–	2.4	3.4	mA	VDDD = 3.0 V, buck ON, Max at 60°C
SIDC4	I _{DD6}	Execute from cache; CM33 Active 8 MHz. IHO. Dhrystone		0.9	1.5		VDDD = 3.0 V, buck ON, Max at 60°C
SIDS1	I _{DD11}	CM33 Sleep 96 MHz with FLL		1.5	2.2		VDDD = 3.0 V, buck ON, Max at 60°C
SIDS2	I _{DD12}	CM33 Sleep 48 MHz with IHO		1.2	1.9		VDDD = 3.0 V, buck ON, Max at 60°C
SIDS3	I _{DD13}	CM33 Sleep 8 MHz with IHO		0.7	1.3		VDDD = 3.0 V, buck ON, Max at 60°C
Deep Sleep mode							
SIDDS1_B	I _{DD33A_B}	With internal buck enabled and 64K SRAM retention	–	6.7	–	μA	At 25°C (with typical Silicon)
SIDDS2_B	I _{DD33B_B}	With internal buck enabled and 128K SRAM retention		7.2			At 25°C (with typical Silicon)
SIDDS5_B	I _{DD33E_B}	With internal buck enabled and 256K SRAM retention		8.5			At 25°C (with typical Silicon)
SIDDS3_B	I _{DD33C_B}	With internal buck enabled and 64K SRAM retention DS-RAM		5.5			At 25°C (with typical Silicon)
SIDDS4_B	I _{DD33D_B}	With internal buck enabled and 128K SRAM retention DS-RAM		6			At 25°C (with typical Silicon)
SIDDS6_B	I _{DD33F_B}	With internal buck enabled and 256K SRAM retention DS-RAM	–	7	–	μA	At 25°C (with typical Silicon)
Hibernate mode							
SIDHIB2	I _{DD34A}	VDDD = 3.0 V	–	1.5	–	μA	No clocks running
SIDHIB4	I _{DD35A}	VDDD = 3.0 V		2			WCO is running

Note

5. Usage above the absolute maximum conditions listed in [Table 10](#) may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150°C in compliance with JEDEC Standard JESD22-A103, high temperature storage life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

Electrical specifications

Table 11 Power supply range, CPU current, and transition time specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
Power mode transition times							
SID13A	T _{DS_ACT}	Deep Sleep to Active transition time. Guaranteed by design.	–	45	60	μs	DS to active with 1.0 V operation, with upper inrush current limit
SID13B	T _{DS_ACTLP}	Deep Sleep to Active LP transition time. Guaranteed by design.		20	35		DS to active LP with 0.9 V operation
SID13C	T _{DSR_ACT}	Deep Sleep-RAM to Active transition time. Guaranteed by design.		–	800		DS to active with 1.0 V operation, with upper inrush current limit
SID13D	T _{DSR_ACTLP}	Deep Sleep-RAM to Active LP transition time. Guaranteed by Design.		–	800		DS-RAM to active LP with 0.9 V operation
SID14	T _{HIB_ACT}	Hibernate to Active transition time		2000	–		Hibernate to active with 1.0 V operation, with upper inrush current limit
SID14A	T _{HIB_ACTLP}	Hibernate to Active LP transition time		2000	–		Hibernate to active with 0.9 V operation, with upper inrush current limit

Note

5. Usage above the absolute maximum conditions listed in [Table 10](#) may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150°C in compliance with JEDEC Standard JESD22-A103, high temperature storage life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

6.2.1 Recommended component

Table 12 Recommended component

Parameter	Conditions	Min	Typ	Max	Unit
LX_BUCK external inductor, L1	4.7 μH ±20%, DCR = 230 mΩ ± 20% (for frequency < 1 MHz), automotive grade	–	4.7	–	μH
LX_BUCK external output capacitor, C11	4.7 μF ±20%, 6.3 V, 0402 inch, X6S, MLCC capacitor	–	4.7	–	μF
VCC_BUCK external input capacitor C35	10 μF ± 20%, 6.3 V, 0402 inch, X6S	–	10	–	

Electrical specifications

6.2.2 XRES

Table 13 XRES DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID17A	T _{XRES_IDD_1}	IDD when XRES asserted	–	800	–	nA	VDDD = 3.3 V
SID77	V _{IH}	Input voltage HIGH threshold	0.7 × VDDIO	–		V	CMOS input
SID78	V _{IL}	Input voltage LOW threshold	–		0.3 × VDDIO		
SID80	C _{IN}	Input capacitance		3	–	pF	–
SID81	V _{HYSXRES}	Input voltage hysteresis		100	mV		
SID82	I _{DIODE}	Current through protection diode to VDDIO/V _{SS}		–	100	μA	

Table 14 XRES AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID15	T _{XRES_ACT}	POR or XRES release to Active transition time	–	1000	–	μs	Normal mode, 96 MHz M33, upper inrush current
SID16	T _{XRES_PW}	XRES pulse width	5	–			–

Electrical specifications

6.2.3 GPIO

Table 15 GPIO DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/ conditions
SID57	V _{IH}	Input voltage HIGH threshold	0.7 × VDDIO	–	–	V	CMOS input
SID57A	I _{IHS}	Input current when Pad > VDDIO for OVT inputs	–		10	μA	Per I ² C spec
SID58	V _{IL}	Input voltage LOW threshold			0.3 × VDDIO	V	CMOS input
SID241	V _{IH}	LVTTL input, VDDIO = 2.7 V	0.7 × VDDIO		–		–
SID242	V _{IL}		–		0.3 × VDDIO		
SID243	V _{IH}	LVTTL input, VDDIO > 2.7 V	2.0		–		
SID244	V _{IL}		–		0.8		
SID59	V _{OH}	Output voltage high level	VDDIO – 0.5		–	–	I _{OH} = 8 mA
SID62A	V _{OL}	Output voltage low level	–		0.4		I _{OL} = 8 mA
SID63	R _{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	–
SID64	R _{PULLDOWN}	Pull-down resistor					
SID65	I _{IL}	Input leakage current (absolute value)	–	–	2	nA	25°C, VDDIO = 3.0 V
SID66	C _{IN}	Input capacitance			5	pF	–
SID67	V _{HYSTTL}	Input hysteresis LVTTL VDDIO > 2.7 V	100	0	–	mV	
SID68	V _{HYSCMOS}	Input hysteresis CMOS	0.05 × VDDIO	–			
SID69	I _{DIODE}	Current through protection diode to VDDIO/V _{SS}	–		100	μA	
SID69A	I _{TOT_GPIO}	Maximum total source or sink chip current			200	mA	

Electrical specifications

Table 16 GPIO AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID70	T _{RISEF}	Rise time in Fast Strong mode, 10% to 90% of VDDIO	–	3.5	–	ns	C _{LOAD} = 15 pF, 8 mA drive strength, VDDIO > 2.7 V
SID70A	T _{RISEF_1}			5.5			C _{LOAD} = 15pF, VDDIO = 2.7 V, max slew and drive strength
SID71	T _{FALLF}	Fall time in Fast Strong mode, 10% to 90% of VDDIO		3.5			C _{LOAD} = 15 pF, 8 mA drive strength, VDDIO > 2.7 V
SID71A	T _{FALLF_1}			5.5			C _{LOAD} = 15pF, VDDIO = 2.7 V, max slew and drive strength
SID72	T _{RISES_1}	Rise time in Slow Strong mode, 10% to 90% of VDDIO	52	–	142		C _{LOAD} = 15 pF, 8 mA drive strength, VDDIO = 2.7 V
SID72A	T _{RISES_2}		48		102		C _{LOAD} = 15 pF, 8 mA drive strength, 2.7 V < VDDIO ≤ 3.6
SID73	T _{FALLS_1}	Fall time in Slow Strong mode, 10% to 90% of VDDIO	44		211		C _{LOAD} = 15 pF, 8 mA drive strength, VDDIO = 2.7 V
SID74	F _{GPIOUT1}	GPIO Fout; Fast Strong mode	–			100	MHz
SID75	F _{GPIOUT2}	GPIO Fout; Slow Strong mode		1.5			
SID76	F _{GPIOUT3}	GPIO Fout; Fast Strong mode		100			
SID245	F _{GPIOUT4}	GPIO Fout; Slow Strong mode		1.3			
SID246	F _{GPIOIN}	GPIO input operating frequency; 2.7 V ≤ VDDIO ≤ 3.6 V				100	

Electrical specifications

6.3 Analog peripherals

Table 17 Internal reference specification

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID93R	V _{REFBG}	–	1.188	1.2	1.212	V	–

6.3.1 AUD ADC

Table 18 MIC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
MIC specifications							
DM.4	-	Audio/Mic supply - ADC_VDD	2.7	-	3.3	V	-
DM.5		Current consumption	-	1.5	-	mA	25°C, ADC_VDD = 3 V, excludes MIC_BIAS loading current
DM.6		Power down current		0.1		µA	25°C, ADC_VDD = 3 V
DM.21		MIC PGA gain range	0	-	42	dB	-
DM.22		MIC PGA gain step	-	1	-		
DM.23		MIC PGA gain error		±1			
DM.24		PGA input referred noise	-	-	4	µV	@ 42 dB PGA gain A-weighted
DM.25		Passband gain flatness			-	dB	PGA + ADC, 100-4 kHz
DM.26		MIC_BIAS output voltage - ADC_VDD × 0.75 × 1.12		2.7		-	V
DM.27		MIC bias loading current		-	3	mA	-
DM.28		MIC_BIAS noise				µV	Referred to PGA input, 20-8 kHz, A-weighted
DM.29		MIC_BIAS PSRR				-	dB

Electrical specifications

Table 19 ADC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
DM.2	-	Analog supply voltage - ADC_VDD	2.7	-	3.6	V	-
DM.5a		Active current consumption - ADC_VDD	-	0.5	-	mA	25°C, ADC_VDD = 3 V
DM.6		Power down current - ADC_VDD		0.1		µA	25°C - ADC disabled with device in Active mode
DM.8		Absolute error - Includes gain error, offset and distortion		-	-	5	%
DM.10		ENOB - Audio application	-	12	-	Bit	
DM.11		ENOB - Static application		11			
DM.12		ADC input full scale - Audio application		1.6		Vpp	
DM.13		ADC input full scale - Static application	0	-	ADC_VDD		
DM.14		Conversion rate - Audio application	16	48	-	kHz	
DM.15		Conversion rate - Static application	50	100	-		
DM.16		Signal bandwidth - Audio application	20	-	8000	Hz	
DM.17		Signal Bandwidth - Static Application	-	DC	-	Hz	
DM.18		Startup time - Audio appli- cation		10		ms	
DM.19		Startup time Static appli- cation		20		µs	
DM.30		ADC SNR	78	-		dB	0 dB PGA gain, A-weighted
DM.31		ADC THD+N	74				-3 dB FS input, 0 dB PGA gain
DM.33		GPIO source impedance	-			1k	Ohm

Electrical specifications

6.4 Digital peripherals

Table 20 Timer/counter/PWM (TCPWM) specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID.TCPWM.1	I _{TCPWM1}	Block current consumption at 8 MHz	–		70	μA	All modes (TCPWM)
SID.TCPWM.2	I _{TCPWM2}	Block current consumption at 24 MHz			180		
SID.TCPWM.2A	I _{TCPWM3}	Block current consumption at 50 MHz			270		
SID.TCPWM.2B	I _{TCPWM4}	Block current consumption at 100 MHz			540		
SID.TCPWM.3	TCPWM _{FREQ}	Operating frequency			100	MHz	Fc max = Fcpu Maximum = 100 MHz
SID.TCPWM.4	TPWM _{ENEXT}	Input trigger pulse width for all trigger events	2 / Fc	–		ns	Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.
SID.TCPWM.5	TPWM _{EXT}	Output trigger pulse widths	1.5 / Fc				Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) trigger outputs
SID.TCPWM.5A	TC _{RES}	Resolution of counter	1 / Fc				Minimum time between successive counts
SID.TCPWM.5B	PWM _{RES}	PWM resolution					Minimum pulse width of PWM output

Electrical specifications

Table 21 Serial communication block (SCB) specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
I ² C DC specifications							
SID149	I _{I2C1}	Block current consumption at 100 kHz	–	–	30	μA	–
SID150	I _{I2C2}	Block current consumption at 400 kHz			80		
SID151	I _{I2C3}	Block current consumption at 1 Mbps			180		
SID152	I _{I2C4}	I ² C enabled in Deep Sleep mode			1.7		At 60°C
I ² C AC specifications							
SID153	F _{I2C1}	Bit rate	–	–	1	Mbps	–
UART DC specifications							
SID160	I _{UART1}	Block current consumption at 100 kbps	–	–	30	μA	–
SID161	I _{UART2}	Block current consumption at 1000 kbps			180		
UART AC specifications							
SID162A	F _{UART1}	Bit rate	–	–	3	Mbps	ULP mode
SID162B	F _{UART2}				8	Mbps	LP mode
SPI DC specifications							
SID163	I _{SPI1}	Block current consumption at 1 Mbps	–	–	220	μA	–
SID164	I _{SPI2}	Block current consumption at 4 Mbps			340		
SID165	I _{SPI3}	Block current consumption at 8 Mbps			360		
SID165A	I _{SPI4}	Block current consumption at 25 Mbps			800		
SPI AC specifications for LP mode (VCCD = 1.1 V) unless noted otherwise							
SID166	F _{SPI}	SPI operating frequency master and externally clocked Slave	–	–	24	MHz	–
SID166B	F _{SPI_EXT}	SPI operating frequency Master (Fscb is SPI clock)			Fscb/4		Fscb max is 96 MHz in LP mode, 24 MHz in ULP mode
SID166A	F _{SPI_IC}	SPI Slave internally clocked			24		–
SPI AC Specifications for ULP Mode (VCCD = 1.0 V) unless noted otherwise							
SID166C	F _{SPI}	SPI operating frequency master and externally clocked Slave	–	–	12	MHz	–
SID166D	F _{SPI_EXT}	SPI operating frequency Master (Fscb is SPI clock)			Fscb/4		Fscb max is 48 MHz in ULP mode
SID166E	F _{SPI_IC}	SPI Slave internally clocked			12		–

Electrical specifications

Table 21 Serial communication block (SCB) specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions	
SPI Master mode AC specifications for LP mode (VCCD = 1.1 V) unless noted otherwise								
SID167	T _{DMO}	MOSI valid after SClock driving edge	–	12	12	ns	20 ns max. for ULP (VCCD = 0.9 V) mode	
SID168	T _{DSI}	MISO valid before SClock capturing edge	20	–	–		Full clock, late MISO sampling	
SID169	T _{HMO}	MOSI data hold time	0		5		Referred to Slave capturing edge	
SID169C	T _{DHI}	SPI master: MISO hold time after SCLK capturing edge	0	–	–	ns	–	
SID169A	T _{SSELMCK1}	SSEL valid to first SCK valid edge	18	21	21		Referred to master clock edge	
SPI Master mode AC Specifications for ULP Mode (1.0 V) unless noted otherwise								
SID167A	T _{DMO}	MOSI valid after SClock driving edge	–	–	26	ns	–	
SID167B	T _{DSI}	MISO valid before SClock capturing edge	35	–	–		–	
SID167C	T _{HMO}	MOSI data hold time	–	-5	–		–	
SID167D	T _{DHI}	SPI master: MISO hold time after SCLK capturing edge	0	–	–		–	
SID167E	T _{SSELMCK1}	SSEL valid to first SCK valid edge	41	–	–		–	
SID167F	T _{SSELMCK2}	SPI SCLK pulse width HIGH	41	–	–		–	
SPI Slave mode AC specifications for LP mode (VCCD = 1.1 V) unless noted otherwise								
SID170	T _{DMI}	MOSI valid before Sclock capturing edge	5	–	–	ns	–	
SID170A	SPI_FREQ	For LP mode	48		–	MHz		
SID171A	T _{DSO_EXT}	MISO valid after Sclock driving edge in External clock mode	–		–	20	ns	35 ns max. for ULP (1.0 V) mode
SID171	T _{DSO}	MISO valid after Sclock driving edge in Internally clock mode				TDSO_EXT + 3 × Tscb		Tscb is Serial Communication Block clock period
SID171B	T _{DSO}	MISO valid after Sclock driving edge in Internally clock mode with median filter enabled				TDSO_EXT + 4 × Tscb		Tscb is Serial Communication Block clock period
SID172	T _{HSO}	Previous MISO data hold time	–			–		
SID172C	T _{HIS}	SPI MOSI hold from SCLK						
SPI Slave mode AC Specifications for ULP Mode (1.0 V) unless noted otherwise								
SID173A	T _{DMI}	MOSI valid before Sclock capturing edge	12	–	–	ns	–	
SID174A	T _{DSO_EXT}	MISO valid after Sclock driving edge in Ext. Clk. mode	–	–	35	ns	–	

Electrical specifications
Table 21 **Serial communication block (SCB) specifications** *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID174	T _{DSO}	MISO valid after Sclock driving edge in internally Clk. mode	–	–	TDSO_EXT + 3 × Tscb	ns	–
SID174B	T _{DSO}	MISO valid after Sclock driving edge in internally Clk. mode with median filter enables	–	–	TDSO_EXT + 4 × Tscb	ns	–
SID175	T _{HISO}	Previous MISO data hold me	5.5	–	–	ns	–
SID175C	T _{HIS}	SPI MOSI hold from SCLK	5.5	–	–	ns	–
SID175D	CSPI	SPI capacitive load		10	–	pF	–

Electrical specifications

6.5 Audio subsystem

Table 22 Audio subsystem specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
PDM specifications							
SID400P	Fmax_clk_sys	Clock frequency for clk_sys	–	96	–	MHz	PVT18 ss, 0.90 V, –40°C, scl40 library, minimum param- eters
SID401	Fmax_clk_if_srss	Clock frequency for Audio clock reference clk_if_srss		48	–	MHz	PVT18 ss, 0.90 V, –40°C, scl40 library, minimum param- eters
SID402	Idyn_act_typ	Typical dynamic current when cell is active. See the DC spec table for related static current spec, if applicable.		–	110	μA/ MHz	PVT16 tt, 1.1 V, 25°C, scl40 library, typical param- eters clk_Audio: 49.152 MHz clk_sys: 50 MHz
SID403	Idyn_act_max	Maximum dynamic active current. See the DC spec table for related static current spec, if applicable.			132		PVT20 ff, 1.21 V, 150°C, scl40 library, maximum param- eters clk_Audio: 49.152 MHz clk_sys: 50 MHz
SID403A	Idyn_slp_typ	Typical dynamic current when cell is idle. See the DC spec table for related static current spec, if applicable.			80		PVT16 tt, 1.1 V, 25°C, scl40 library, typical param- eters, clocks toggling clk_Audio: 49.152 MHz clk_sys: 50 MHz
SID403B	T_SETUP	Receiver setup			10	ns	PVT18 ss, 0.90 V, –40°C, scl40 library, minimum param- eters
SID404A	CPDM	Load		10	–	pF	–
SID404	PDM_OUT	Audio sample rate	8	–	48	ksps	–
SID405	PDM_WL	Word length	16	–	24	bits	–
SID412	PDM_ST	Startup time	–	48	–	–	WS (Word Select) cycles

Note

6. TMCLK_SOC is the internal I2S master clock period.

Electrical specifications

Table 22 Audio subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
I ² S specifications, the same for LP and ULP modes unless stated otherwise.							
SID413	I2S_WORD	Length of I ² S word	8	–	32	bits	–
SID414B	I2S_BCK_F	Bit clock frequency in LP mode	–		12.288	MHz	
SID414BU	I2S_BCK_F_U	Bit clock frequency in ULP mode			3.072		
SID414BP	I2S_BCK_P	Bit clock period		1/I2S_BCK_F	–	ns	
SID414BPU	I2S_BCK_P_U	Bit clock period in ULP mode		1/I2S_BCK_F_U			
SID414	I2S_WS_FREQ	Word clock frequency in LP mode		–	192	kHz	
SID414M	I2S_WS_FREQ_U	Word clock frequency in ULP mode			48		
SID435L	I2S_BCK_TL	Bit clock low period in LP mode	0.35 × I2S_BCK_P	–	–	ns	–
SID415IL	I2S_MCKI_TL	Master clock IN low period in LP (or) ULP mode	0.45 × tMCLK				
SID415IH	I2S_MCKI_TH	Master clock IN high period in LP (or) ULP Mode					
SID415OL	I2S_MCKO_TL	Master clock Out low period in LP (or) ULP mode	0.35 × tMCLK	0.45 × tMCLK to 0.4 × tMCLK			
SID415OH	I2S_MCKO_TH	Master clock Out high period in LP (or) ULP mode					
SID416	TDM_OUTPUT_LOAD_MAX	Capacitive load	10	–		pF	–
I2S Slave mode							
SID430	I2S_S_TS_WS	WS setup time before the first edge following the driving edge of bit clock for LP Mode	0.2 × I2S_BCK_P	–	–	ns	–
SID430U	I2S_S_TS_WS_U	WS setup time before the first edge following the driving edge of bit clock for ULP mode	0.2 × I2S_BCK_P_U				

Note

6. TMCLK_SOC is the internal I2S master clock period.

Electrical specifications

Table 22 Audio subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID430A	I2S_S_TH_WS	WS Hold time after the first edge following the driving edge of bit clock, LP or ULP mode	0	–	–	ns	–
SID432	I2S_S_SDO	SDO Propagation delay from driving edge of bit clock for LP mode	$0.3 \times \text{I2S_BCK_P}$		$0.2 \times \text{I2S_BCK_P}$		
SID432U	I2S_S_SDO_U	SDO Propagation delay from driving edge of bit clock for ULP mode	$0.3 \times \text{I2S_BCK_P_U}$		$0.2 \times \text{I2S_BCK_P_U}$		

I2S Master mode

SID437	I2S_M_WS	WS propagation delay from driving edge of bit clock for LP mode	0	–	$0.2 \times \text{I2S_BCK_P}$	ns	–
SID437_U	I2S_M_WS_U	WS propagation delay from driving edge of bit clock for ULP mode			$0.2 \times \text{I2S_BCK_P_U}$		
SID438	I2S_M_SDO	SDO Propagation delay from driving edge of bit clock for LP mode			$0.2 \times \text{I2S_BCK_P}$		
SID438U	I2S_M_SDO_U	SDO Propagation delay from driving edge of bit clock for ULP mode			$0.2 \times \text{I2S_BCK_P_U}$		Associated clock edge depends on selected polarity

Note

6. TMCLK_SOC is the internal I2S master clock period.

Electrical specifications

6.6 System resources

6.6.1 Power-on reset

Table 23 Power-on reset (POR) with brownout detect (BOD) DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
Precise POR (PPOR)							
SID190	V _{FALLPPOR}	BOD trip voltage in Active and Sleep modes VDDD	1.54	–	–	V	BOD reset guaranteed for VDDD levels below 1.54 V.
SID192	V _{FALLDPSLP}	BOD trip voltage in Deep Sleep VDDD	1.54				–
SID192A	V _{DDRAMP}	Maximum power supply ramp rate (any supply)	–		100	mV/ μs	Active mode

Table 24 POR with BOD AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID194A	V _{DDRAMP_DS}	Maximum power supply ramp rate (any supply) in system Deep Sleep mode	–	–	10	mV/ μs	BOD operation guaranteed

6.6.2 Voltage monitors

Table 25 Voltage monitors DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID195	V _{HVDI1}	–	1.38	1.43	1.47	V	–
SID196	V _{HVDI2}		1.57	1.63	1.68		
SID197	V _{HVDI3}		1.76	1.83	1.89		
SID198	V _{HVDI4}		1.95	2.03	2.10		
SID199	V _{HVDI5}		2.05	2.13	2.2		
SID200	V _{HVDI6}		2.15	2.23	2.3		
SID201	V _{HVDI7}		2.24	2.33	2.41		
SID202	V _{HVDI8}		2.34	2.43	2.51		
SID203	V _{HVDI9}		2.44	2.53	2.61		
SID204	V _{HVDI10}		2.53	2.63	2.72		
SID205	V _{HVDI11}		2.63	2.73	2.82		
SID206	V _{HVDI12}		2.73	2.83	2.92		
SID207	V _{HVDI13}		2.82	2.93	3.03		
SID208	V _{HVDI14}		2.92	3.03	3.13		
SID209	V _{HVDI15}		3.02	3.13	3.23		
SID211	LVI_IDD	Block current	–	5	15	μA	

Table 26 Voltage monitors AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID212	T _{MONTRIP}	Voltage monitor trip time	–	–	170	ns	–

Electrical specifications

6.6.3 SWD and trace interface

Table 27 SWD and trace specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID214	F_SWCLK2	2.7 V ≤ VDDD ≤ 3.6 V	–	–	25	MHz	LP mode; VCCD = 1.1 V
SID214L	F_SWCLK2L				12		ULP mode; VCCD = 1.0 V
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	–		ns	For both LP and ULP modes	
SID216	T_SWDI_HOLD		–				
SID217	T_SWDO_VALID		–				–
SID217A	T_SWDO_HOLD		1				–
SID214T	F_TRCLK_LP1	With trace data setup/hold times of 2/1 ns respectively	–		48	MHz	LP mode, VCCD = 1.1 V
SID215T	F_TRCLK_LP2	With trace data setup/hold times of 3/2 ns respectively			48		
SID216T	F_TRCLK_ULP				24		ULP mode, VCCD = 1.0 V

6.6.4 Internal main oscillator

Table 28 IMO DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID218	I _{IMO1}	IMO operating current at 8 MHz	–	9	15	μA	–

Table 29 IMO AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID223	FIMOTOL1	Frequency variation centered on 8 MHz	–	–	±2	%	–
SID227	T _{JITR}	Cycle-to-cycle and period jitter	–	±250	–	μs	

6.6.5 Internal low-speed oscillator

Table 30 ILO DC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID231	I _{ILO2}	ILO operating current at 32 kHz	–	0.3	0.7	μA	–

Table 31 ILO AC specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID234	T _{STARTILO1}	ILO startup time	–	–	7	μs	Startup time to 80% of final frequency
			–	–	35	μs	Startup time to 95% of final frequency
SID236	T _{LIODUTY}	ILO duty cycle	45	50	55	%	–
SID237	F _{ILOTRIM1}	32 kHz trimmed frequency	28.8	32	35.2	kHz	±10% variations

Electrical specifications

6.6.6 FLL

Table 32 Frequency locked loop (FLL) specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions	
SID450	FLL_RANGE	Input frequency range	0.040	-	96.00	MHz	Upper limit is for External input	
SID451	FLL_OUT_DIV2	Output frequency range. VCCD = 1.1 V	24.00				48.00	Output range of FLL divided-by-2 output
SID451A	FLL_OUT_DIV2	Output frequency range. VCCD = 0.9 V						
SID452	FLL_DUTY_DIV2	Divided-by-2 output; HIGH or LOW	47.00		53.00	%	-	
SID454	FLL_WAKEUP	Time from stable input clock to 1% of final value on Deep Sleep wakeup	-		11.00	μs	With IMO input, less than 10°C change in temperature while in Deep Sleep, and Fout ≥ 50 MHz	
SID455	FLL_JITTER	Period jitter (1 sigma at 100 MHz)			18.00	ps	-	
SID456	FLL_CURRENT	CCO + logic current			5.50	μA/ MHz		

6.6.7 Crystal oscillator

Table 33 ECO specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/ conditions
MHz ECO DC specifications							
SID316	I _{DD_MHz}	Block operating current with Cload up to 18 pF	–	1200	–	μA	Type 24 MHz
MHz ECO AC specifications							
SID317	F_MHz	Crystal frequency range	–	24	–	MHz	–
kHz ECO DC specifications							
SID318	IDD_kHz	Block operating current with 32-kHz crystal	–	0.38	1	μA	–
SID321E	ESR32K	Equivalent series resistance		80	–	kΩ	
SID322E	PD32K	Drive level		–	0.5	μW	
kHz ECO AC specifications							
SID319	F_kHz	32-kHz trimmed frequency	–	32.8	–	kHz	–
SID320	Ton_kHz	Startup time		–	1000	ms	
SID320E	F _{TOL32K}	Frequency tolerance		50	250	ppm	

Electrical specifications

6.6.8 Clock source switching time

Table 34 Clock source switching time specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID262	TCLK _{SWITCH}	Clock switching from one CLK_HF to another CLK_HF in clock periods ^[7]	–	–	4 clk1 + 3 clk2	periods	–

Note

7. For example, if the clk_path[1] source is changed from the IMO to the FLL (see [Figure 3](#)) then clk1 is the IMO and clk2 is the FLL.

6.6.9 QSPI

Table 35 QSPI specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/ conditions
QSPI specifications - All specs with 15-pF load							
SID390Q	Fsmifclock	QSPI output clock frequency	–	–	48	MHz	LP mode (VCCD = 1.1 V)
SID390QU	Fsmifclocku	QSPI output clock frequency			24		ULP mode (VCCD = 1.0 V)
SID397Q	Idd_qspi	Block current in LP mode (1.0 V)			1900	μA	LP mode (VCCD = 1.1 V)
SID398Q	Idd_qspi_u	Block current in ULP mode (0.9 V)			590		ULP mode (VCCD = 1.0 V)
SID399A	SDR_TCSH0	CS# active hold to CK	4	–	–	ns	–
SID399B	SDR_TOUT_ SETUP_LF	Output setup time of DQ[3:0] to CK high	5.1				
SID399C	SDR_TOUT_ HOLD_LF	Output hold time of DQ[3:0] to CK high					
SID399D	SDR_TIN_V	CK low to DQ[3:0] input valid time	–				
SID399E	SDR_TIN_HO	CK low to DQ[3:0] input hold time	1				

6.6.10 Smart I/O

Table 36 Smart I/O specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID420	SMIO_BYP	Smart I/O bypass delay	–	–	2	ns	–
SID421	SMIO_LUT	Smart I/O LUT prop delay					

Electrical specifications

6.6.11 JTAG boundary scan

Table 37 JTAG boundary scan

Spec ID#		Parameter	Min	Typ	Max	Unit	Description	
JTAG boundary scan parameters								
SID460	TCKLOW	TCK LOW minimum	34	-	-	ns	-	
SID461	TCKHIGH	TCK HIGH	10					
SID462	TCK_TDO	TDO clock-to-out (max) from falling TCK	-		22			
SID463	TSU_TCK	TDI, TMS Setup time before rising TCK	12					
SID464	Tck_THD	TDI, TMS Hold time after rising TCK	10					
SID465	TCK_TDOV	TCK to TDO data valid (High-Z to active)	22		-			
SID466	TCK_TDOZ	TCK to TDO data valid (Active to High-Z).						
JTAG boundary scan parameters for LP (VCCD = 1.1 V) mode operation								
SID468	TCKLOW	TCK LOW	52	-	-	ns	-	
SID469	TCKHIGH	TCK HIGH	10					
SID469A	TCKPERIOD	CLK_JTAG_PERIOD, 30 pF load	-	62				
SID470	TCK_TDO	TCK falling edge to output valid		-	40			
SID471	TSU_TCK	Input valid to TCK rising edge	12					
SID472	Tck_THD	Input hold time to TCK rising edge	10					
SID473	TCK_TDOV	TCK falling edge to output valid (High-Z to Active)	40					
JTAG boundary scan p for ULP (VCCD = 1.0 V) mode operation								
SID468A	TCKLOW	TCK LOW	102	-	-	ns	-	
SID469A	TCKHIGH	TCK HIGH	20					
SID470A	TCK_TDO	TCK falling edge to output valid	-		80			
SID471A	TSU_TCK	Input valid to TCK rising edge	22					
SID472A	Tck_THD	Input hold time to TCK rising edge	20	-	-	ns	-	
SID473A	TCK_TDOV	TCK falling edge to output valid (High-Z to Active)	80					
SID474A	TCK_TDOZ	TCK falling edge to output valid (Active to High-Z)						

Electrical specifications

6.7 Bluetooth® LE

Table 38 Bluetooth® LE subsystem specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
RF receiver specifications (1 Mbps)							
SID317R ^[8]	RXS, IDLE	RX sensitivity with ideal transmitter	–	–98	–	dBm	Across RF operating frequency range
SID318R ^[9]				–96.5			
SID319R	PRXMAX	Maximum received signal strength at < 30.8% PER		–5		RF-PHY specification (RCV-LE/CA/06/C)	
SID320R	CI1	Co-channel interference, wanted signal at -67 dBm and interferer at FRX		9	21	dB	RF-PHY specification (RCV-LE/CA/03/C)
SID321R	CI2	Adjacent channel interference, wanted signal at -67 dBm and interferer at FRX ± 1 MHz		–3	15		
SID322R	CI3	Adjacent channel interference, wanted signal at -67 dBm and interferer at FRX ± 2 MHz		–45	–17		
SID323R	CI4	Adjacent channel interference, wanted signal at -67 dBm and interferer at ≥ FRX ± 3 MHz		–49	–27		
SID324R	CI5	Adjacent channel interference, wanted signal at -67 dBm and interferer at image frequency (FIMAGE)	–31	–9			
SID325R	CI6	Adjacent channel interference, wanted signal at -67 dBm and interferer at image frequency (FIMAGE ± 1 MHz)	–35	–15			
RF receiver specifications (2 Mbps)							
SID326 ^[8]	RXS, IDLE	RX sensitivity with ideal transmitter	–	–95	–	dBm	Across RF operating frequency range
SID327 ^[9]				–93.5			
SID328R	PRXMAX	Maximum received signal strength at < 30.8% PER		–5		RF-PHY specification (RCV-LE/CA/06/C)	

Notes

8. Coherent demodulator enabled with stable modulation index.

9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID329R	CI1	Co-channel interference, wanted signal at -67 dBm and interferer at FRX	-	7	21	dB	RF-PHY specification (RCV-LE/CA/03/C)
SID330	CI2	Adjacent channel interference, wanted signal at -67 dBm and interferer at $FRX \pm 2$ MHz		-2	15		
SID331	CI3	Adjacent channel interference, wanted signal at -67 dBm and interferer at $FRX \pm 4$ MHz		-42	-15		
SID332	CI4	Adjacent channel interference, wanted signal at -67 dBm and interferer at $\geq FRX \pm 6$ MHz		-42	-27		
SID333	CI5	Adjacent channel interference, wanted signal at -67 dBm and interferer at Image frequency (FIMAGE)		-29	-9		
SID334	CI6	Adjacent channel interference, wanted signal at -67 dBm and interferer at Image frequency (FIMAGE ± 2 MHz)		-40	-15		

RF receiver specification S2 (500 kbps)

SID501	RXS, IDLE	RX sensitivity with Ideal transmitter, standard Mod index RX	-	-101	-	dBm	Across RF operating frequency range
SID506	CI1	Co-channel interference, wanted signal at -72 dBm and interferer at FRX		3	17	dB	RF-PHY specification (RCV-LE/CA/28/C)
SID507	CI2	Adjacent channel interference, wanted signal at -72 dBm and interferer at $FRX \pm 1$ MHz		-11	11		
SID508	CI3	Adjacent channel interference, wanted signal at -72 dBm and interferer at $FRX \pm 2$ MHz		-50	-21		
SID509	CI4	Adjacent channel interference, wanted signal at -72 dBm and interferer at $FRX \pm 3$ MHz		-53	-31		

Notes

8. Coherent demodulator enabled with stable modulation index.
 9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID510	CI5	Adjacent channel interference, wanted signal at -72 dBm and interferer at image frequency (FIMAGE)	-	-37	-13	dB	RF-PHY specification (RCV-LE/CA/28/C)
SID511	CI6	Adjacent channel interference, wanted signal at -72 dBm and interferer at image frequency (FIMAGE ± 1MHz)		-42	-19		

RF receiver specification S8 (125 kbps)

SID512	RXS, IDLE	RX sensitivity with ideal transmitter ^[9]	-	-106	-	dBm	Across RF operating frequency range
SID517	CI1	Co-channel interference, wanted signal at -79 dBm and interferer at FRX		6	12	dB	RF-PHY specification (RCV-LE/CA/29/C)
SID518	CI2	Adjacent channel interference wanted signal at -79 dBm and interferer at FRX ± 1MHz		-18	6		
SID519	CI3	Adjacent channel interference wanted signal at -79 dBm and interferer at FRX ± 2 MHz		-52	-26		
SID520	CI4	Adjacent channel interference wanted signal at -79 dBm and interferer at FRX ± 3 MHz		-51	36		
SID521	CI5	Adjacent channel interference wanted signal at -79 dBm and interferer at Image frequency (FIMAGE)		-40	-18		
SID522	CI6	Adjacent channel interference wanted signal at -79 dBm and interferer at Image frequency (FIMAGE ± 1MHz)		-47	-24		

Notes

8. Coherent demodulator enabled with stable modulation index.
9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions	
RF Receiver specification (1 and 2 Mbps)								
SID338	OBB1	Out-of-band blocking wanted signal at -67 dBm and interferer at F = 30 -2000 MHz	-30	–	–	dBm	RF-PHY specification (RCV-LE/CA/04/C)	
SID339	OBB2	Out-of-band blocking, wanted signal at -67 dBm and interferer at F = 2003–2399 MHz	-35	–			RF-PHY specification (RCV-LE/CA/04/C)	
SID340	OBB3	Out-of-band blocking, wanted signal at -67 dBm and interferer at F = 2484–2997 MHz	-35					
SID341	OBB4	Out-of-band blocking, wanted signal l at -67 dBm and interferer at F = 3000–12750 MHz	-30					
SID342	IMD	Intermodulation Performance, wanted signal at -64 dBm and 1 Mbps Bluetooth® LE, 3rd, 4th and 5th offset channel	-50	–			RF-PHY specification (RCV-LE/CA/05/C)	
SID343	RXSE1	Receiver spurious emission 30 MHz to 1.0 GHz	–		-57			100 kHz measurement bandwidth ETSI EN300 328 V2.1.1
SID344	RXSE2	Receiver spurious emission 1.0 GHz to 12.75 GHz	–		-53			1 MHz measurement bandwidth ETSI EN300 328 V2.1.1

Notes

8. Coherent demodulator enabled with stable modulation index.
9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
RF transmitter specifications							
SID345	TXP, ACC	RF power accuracy	-2	-	2		-
SID346	TX0	Power range		23		dB	-24 dBm to 0 dBm
	TX10			33			-24 dBm to 10 dBm
SID347	TXP, 0dBm	Output power, 0 dB power setting	-	0	-	dBm	For TX10 mode, BT_PAVDD connected to VCCPA. The minimum supply voltage VDDD is 2.7 V
SID348	TXP, 10dBm	Output power, 10 dBm power setting		10			
SID349	TXP, MIN	Output power, minimum power setting		-20			
SID350	F2Max	Average frequency deviation for 10101010 pattern	185	-		kHz	RF-PHY specification (TRM-LE/CA/05/C)
SID350R	F2Max_2M	Average frequency deviation for 10101010 pattern for 2 Mbps	370				
SID350LR	F1Max_S8	Average frequency deviation for 10101010 pattern for 125 bps	185				
SID351	F1AVG	Average frequency deviation for 11110000 pattern	225	250	275		RF-PHY specification (TRM-LE/CA/05/C)
SID351R	F1AVG_2M	Average frequency deviation for 11110000 pattern for 2 Mbps	450	500	550		RF-PHY specification (TRM-LE/CA/05/C)
SID351R	F1AVG_S8	Average frequency deviation for 11110000 pattern for 125 kbps	225	250	275		RF-PHY specification (TRM-LE/CA/13/C)
SID352	EO	Eye opening = $\Delta F2AVG/\Delta F1AVG$	0.8	-	-	-	RF-PHY specification (TRM-LE/CA/05/C)
SID353	FTX,ACC	Frequency accuracy	-150		150	kHz	RF-PHY specification (TRM-LE/CA/06/C)
SID354	FTX,MAXDR	Maximum frequency drift	-50		50		RF-PHY specification (TRM-LE/CA/06/C)
SID355	FTX, INITDR	Initial frequency drift	-20		20		RF-PHY specification (TRM-LE/CA/06/C)
SID355LR	FTX, INITDR, S8		-19.2		19.2		RF-PHY specification (TRM-LE/CA/14/C)
SID356	FTX, DR	Maximum drift rate	-20		20	kHz/ 50 μ s	RF-PHY specification (TRM-LE/CA/06/C)
	FTX, DR, S8		-19.2		19.2		RF-PHY specification (TRM-LE/CA/14/C)

Notes

8. Coherent demodulator enabled with stable modulation index.
9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID357	IBSE1	In Band Spurious Emission at 2 MHz offset (1 Mbps) In Band Spurious Emission at 4 MHz offset (2 Mbps)	-	-	-20	dBm	RF-PHY specification (TRM-LE/CA/03/C)
SID358	IBSE2	In Band Spurious Emission at > 3 MHz offset (1 Mbps) In Band Spurious Emission at > 6 MHz offset (2 Mbps)			-30		
SID359	TXSE1	Transmitter Spurious Emissions (Averaging), < 1.0 GHz		-	-55.5		FCC-15.247
SID360	TXSE2	Transmitter Spurious Emissions (Averaging), > 1.0 GHz			-41.5		

RF current specifications

SID361	IRX1_wb	Receive current (1 Mbps)	-	5.7	-	mA	Measured with VCC_BUCK = 3.0 V. In all cases, VCCI = 1.16 V and VCCRF = 1.1 V. For TX0, BT_PAVDD = VCCRF. For TX10, BT_PAVDD = VCCPA = 2.5 V.
SID362	ITX1_0dBm	TX current at 0 dBm setting (1 Mbps)		5.2			
SID365R	ITX1_10dBm	TX current at 10 dBm setting (1 Mbps)		19.3			

General RF specifications

SID373	FREQ	RF operating frequency	2402	–	2480	MHz	–
SID374	CHBW	Channel spacing	–	2	–		
SID375	DR1	On-air data rate (1 Mbps)		1000			
SID376	DR2	On-air data rate (2 Mbps)		2000			

RSSI specifications

SID379	RSSI, ACC	RSSI accuracy	-3	-	3	dB	-95 dBm to -20 dBm measurement range
SID380	RSSI, RES	RSSI resolution	-	1	-	dB	-
SID381	RSSI, PER	RSSI sample period	-	6	-	μs	-

System-level Bluetooth® LE specifications

Notes

8. Coherent demodulator enabled with stable modulation index.
9. Coherent demodulator enabled with standard modulation index.

Electrical specifications

Table 38 Bluetooth® LE subsystem specifications (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Unit	Details/conditions
SID433R	Adv_Pwr	Advertising power, 1.28 s advertising interval, 31 bytes, TX 0 dBm	–	44.5	–	μW	Connectible advertising, VBAT = 3.0 V. Measured with WCO
				46			Connectible advertising, VBAT = 3.0 V. Measured with PILO.
SID434R	Conn_Pwr_300	Connection power, 300 ms connection interval, 0 bytes, TX 0 dBm		64.6			VBAT = 3.0 V Measured with WCO.
				68.8			VBAT = 3.0 V. Measured with PILO.
SID435R	Conn_Pwr_1S	Connection power, 1000 ms connection interval, 0 bytes, TX 0 dBm		29.5			VBAT = 3.0 V Measured with WCO.
				31.9			VBAT = 3.0 V. Measured with PILO.

Notes

8. Coherent demodulator enabled with stable modulation index.
9. Coherent demodulator enabled with standard modulation index.

Ordering information

7 Ordering information

Table 39 lists the CYW89829 part numbers and features.

Table 39 **Ordering part numbers**

Product	Package	Ambient operating temperature
CYW89829B0232	8.0 × 7.0 × 1.0 mm 77-BGA	–40°C to 105°C

Note : Part number decoder information

CYW89829Bxabc	0	1	2	3	4	5	6
a - flash memory	No memory	512K	1M	2M	–	–	–
b - PL Reserved (Package Type)	QFN56 Entry	QFN56 Base	QFN40	77BGA	64BGA	eWLB	QFN48
c - Temp grade	Consumer	Industrial	Auto	–	–	–	–

Note

10.T and R device with “T”.

Packaging

8 Packaging

This product line is offered in 77-ball BGA package.

Table 40 Package dimensions

Spec ID#	Package	Description	Package drawing number
PKG_2	77-ball BGA	77-ball BGA, 8.0 × 7.0 × 1.0 mm height with 0.8 mm pitch	002-37897

Table 41 Package characteristics

Parameter	Description	Condition	Min	Typ	Max	Unit
T _A	Operating ambient	–	-40	25	105	°C
T _J	Operating junction			–	125	
T _{JA}	Package θ _{JA} (77-ball BGA)		–	48	–	°C/W
T _{JB}	Package θ _{JB} (77-ball BGA)			15		
T _{JC}	Package θ _{JC} (77-ball BGA)			8		

Table 42 Solder reflow peak temperature

Package	Maximum peak temperature	Maximum time at peak temperature
77-ball BGA	260°C	30 s

Table 43 Package moisture sensitivity level (MSL), IPC/JEDEC J-STD-2

Package	MSL
77-ball BGA	MSL-3

Packaging

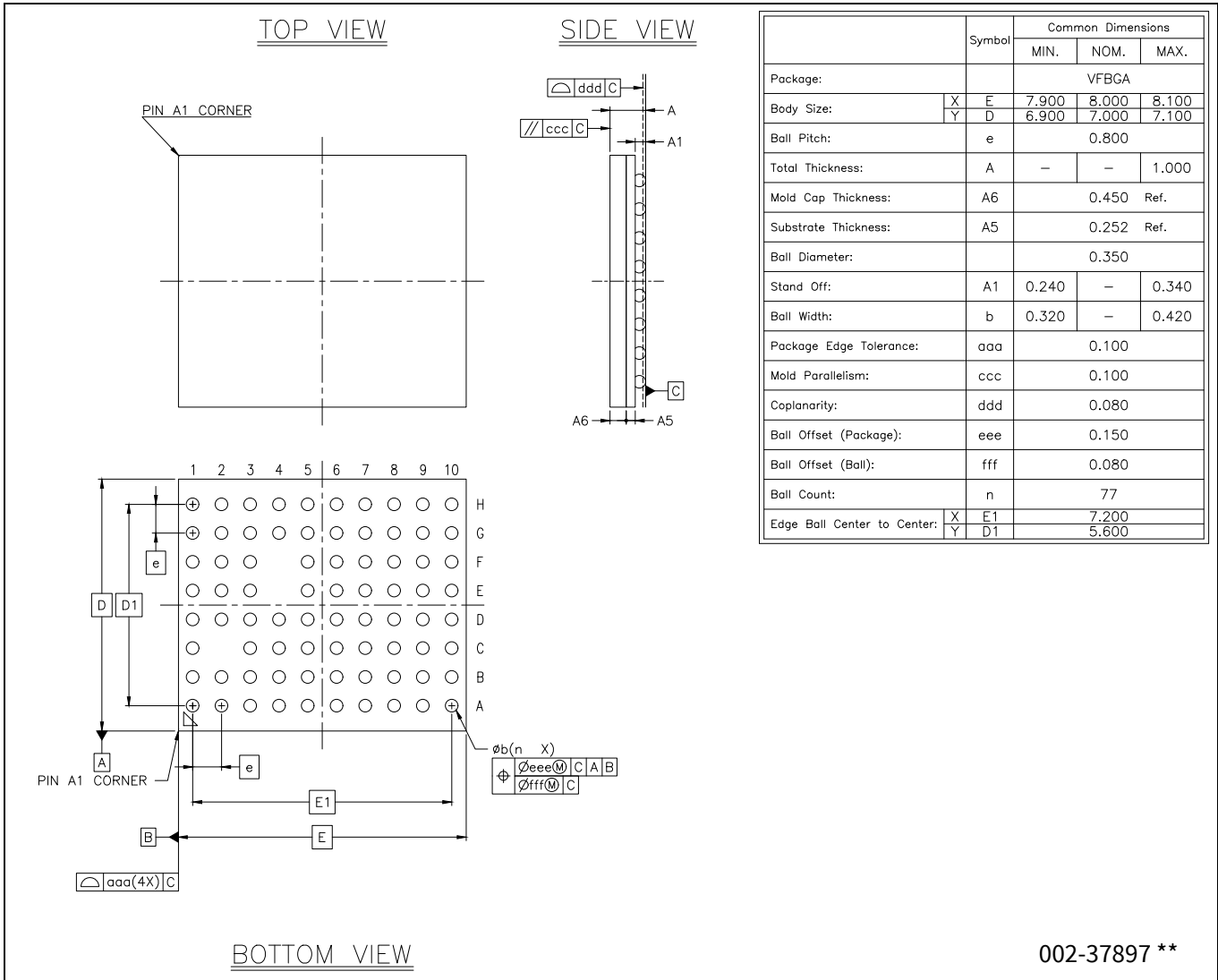


Figure 9 77-ball FBGA (8.0 × 7.0 × 1.0 mm) BZ77A, package outline (PG-VFBGA-77)

Acronyms

9 Acronyms

Table 44 Acronyms used in this document

Acronym	Description
3DES	triple DES (data encryption standard)
ADC	analog-to-digital converter
AES	Advanced encryption standard
AHB	AMBA (advanced microcontroller bus architecture) high-performance bus, an Arm® data transfer bus
API	application programming interface
Arm®	advanced RISC machine, a CPU architecture
BOD	brownout detect
BTSS	Bluetooth® subsystem
CAD	computer aided design
CBC	cipher block chaining
CFB	cipher feedback
CCO	current controlled oscillator
CK	Clock (QSPI)
CM0+	Cortex®-M0+, an Arm® CPU
CM4	Cortex®-M4, an Arm® CPU
CMOS	complementary metal-oxide-semiconductor, a process technology for IC fabrication
CPU	Central Processing Unit
CRC	cyclic redundancy check, an error-checking protocol
CSD	CAPSENSE™ sigma-delta
CTR	Counter
DAC	digital-to-analog converter, see also IDAC, VDAC
DAP	debug access port
DES	data encryption standard
DMA	Direct Memory Access, see also TD
DNL	differential nonlinearity, see also INL
DQ	Data bits
DSI	digital system interconnect
ECB	electronic code book
ECC	elliptic curve cryptography
ECDSA	elliptic curve digital signature algorithm
ECO	external crystal oscillator
EMI	electromagnetic interference
ESD	electrostatic discharge
FIFO	first-in, first-out
FLL	frequency locked loop
FS	Full-speed
GND	Ground

Acronyms

Table 44 Acronyms used in this document (continued)

Acronym	Description
GPIO	general-purpose input/output
HMAC	hash-based message authentication code
HSIOM	high-speed I/O matrix
I/O	input/output, see also GPIO, DIO, SIO, USBIO
I ² C, or IIC	Inter-Integrated Circuit, a communications protocol
I ² S	inter-IC sound
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
IoT	Internet Of Things
IPC	inter-processor communication
IRQ	interrupt request
JTAG	Joint Test Action Group
LIN	Local Interconnect Network, a communications protocol
LP	low-power
LS	low-speed
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	Microcontroller unit
MCWDT	multi-counter watchdog timer
MISO	master-in slave-out
MMIO	memory-mapped input output
MOSI	master-out slave-in
MPU	memory protection unit
MSL	moisture sensitivity level
NMI	nonmaskable interrupt
NVIC	nested vectored interrupt controller
NVM	Non Volatile Memory
OFB	output feedback
OTP	one-time programmable
OVT	overvoltage tolerant
PCB	printed circuit board
PCM	pulse code modulation
PDM	pulse density modulation
PHY	physical layer

Acronyms

Table 44 Acronyms used in this document (continued)

Acronym	Description
PLL	phase-locked loop
POR	power-on reset
PRNG	Pseudo Random Number Generator
PSRR	power supply rejection ratio
PWM	pulse-width modulator
QSPI	Quad Serial Peripheral interface
RAM	random-access memory
RISC	reduced-instruction-set computing
ROM	read-only memory
RTC	real-time clock
RX	receive
SAR	Successive Approximation register
SARMUX	SAR ADC multiplexer bus
SCB	Serial Communication Block
SHA	secure hash algorithm
SNR	signal-to-noise ration
SPI	Serial Peripheral Interface, a communications protocol
SRAM	static random access memory
SROM	supervisory read-only memory
SWD	serial wire debug, a test protocol
SWJ	Serial-wire JTAG
SWO	single wire output
SWV	Serial-wire viewer
TCPWM	timer, counter, pulse-width modulator
TDM	time division multiplexed
TRM	technical reference manual
TRNG	True Random Number Generator
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
ULP	ultra-low-power
WCO	watch crystal oscillator
WDT	watchdog timer
WIC	wakeup interrupt controller
XIP	execute-in-place
XRES	external reset input pin

Document conventions

10 Document conventions

10.1 Units of measure

Table 45 Units of measure

Symbol	Unit of measure
°C	degrees celsius
dB	decibel
fF	femtofarad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
hr	hour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSb	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
μA	microampere
μF	microfarad
μH	microhenry
μs	microsecond
μV	microvolt
μW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

Revision history

Revision history

Document revision	Date	Description of changes
**	2023-06-08	New datasheet.
*A	2023-07-20	Updated Block diagram Updated description. Updated System resources Updated Power system Updated description. Updated Main crystal oscillator Updated description. Updated 32 kHz crystal oscillator Updated description. Updated Pinouts Updated Table 8 . Updated Figure 7 . Updated Power supply considerations Updated description. Updated Electrical specifications Updated Operating conditions Updated Table 11 . Updated Analog peripherals Updated AUD ADC : Updated Table 18 . Updated Table 19 . Updated System resources Updated SWD and trace interface Updated Table 27 .
*B	2023-08-30	Updated Bluetooth® LE subsystem spec. Updated VDDD description.
*C	2023-10-13	Updated Features . Updated Table 3 , Table 11 , Table 31 and Table 38 . Updated Internal low-speed oscillator (ILO) .
*D	2024-04-08	Added Part number "CYW89829B0232ES" in the Table 38 . Updated Features , Functional description , Bluetooth® Low Energy subsystem and Internal low-speed oscillator (ILO) . Updated Figure 1 . Added Precision internal low-speed oscillator (PILO) . Moved Table 7 to GPIO section. Updated Table 8 . Updated the max value in Table 11 . Updated the max value in Table 38 . Updated the max value for TJ in Table 41 .

Revision history

Document revision	Date	Description of changes
*E	2024-09-12	Updated Features section. Updated Power system section. Updated Figure 2. Updated Sigma-delta ADC section. Added note in Serial communication blocks (SCB) section. Updated Drive strength for VDDD = 2.7 V and Drive strength for VDDD > 2.7 V in Table 7. Updated the description for RSVD1 and RSVD2 in Table 8. Updated Table 9. Added SID7F in Table 11. Updated Table 13. Updated the description for SID241 and SID242 in Table 15. Updated the Details/conditions in Table 16. Added Table 18. Updated Table 21, Table 35, Table 37. Added footnote in Table 38. Removed Table 18 ADC specifications. Updated the Typ value for T_{JA} and T_{JC} in Table 41. Added T_{JB} in Table 41. Updated Figure 8.
*F	2024-12-11	Updated Table 38 .
*G	2025-05-02	Removed "Preliminary" status. Updated "8 Mb integrated flash" on page 2. Updated "Serial communication blocks" on page 2. Updated "Memory" on page 10. Added footnote for "Power system" on page 12. Updated note in "Serial communication blocks (SCB)" on page 19. Updated "8 Mb integrated flash" on page 20. Updated Part number in the Table 38.

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